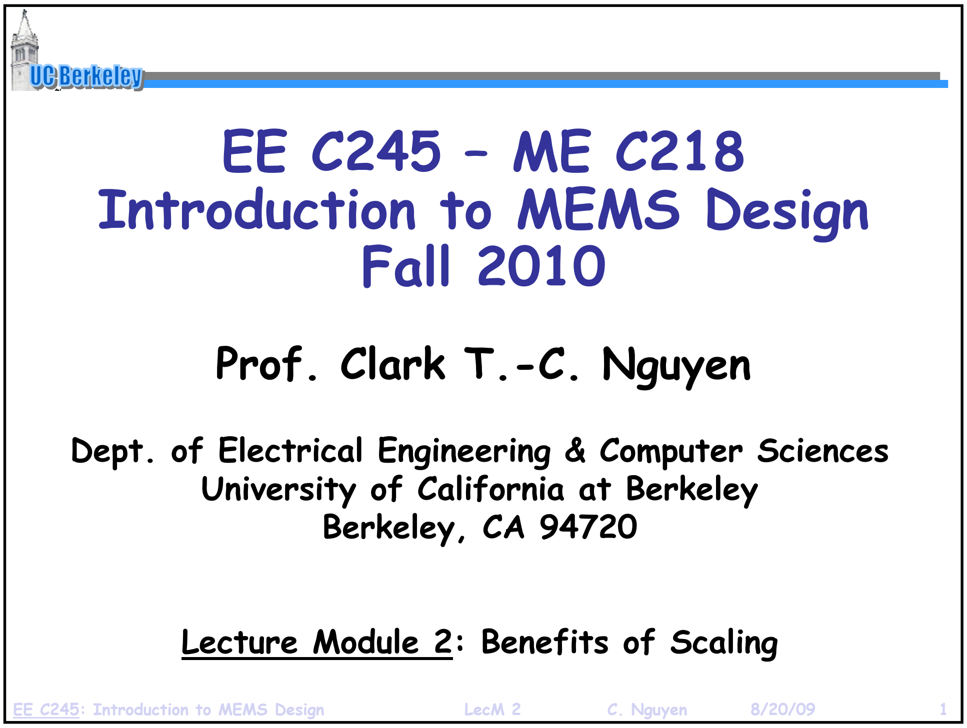

EE C245 – ME C218
Introduction to MEMS Design
Fall 2010

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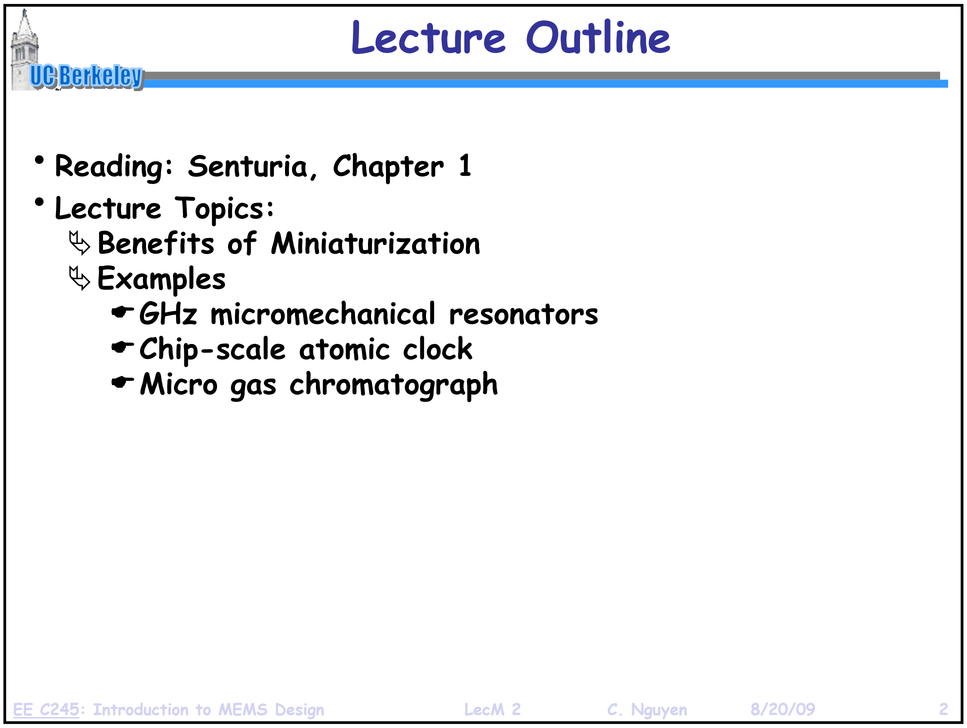
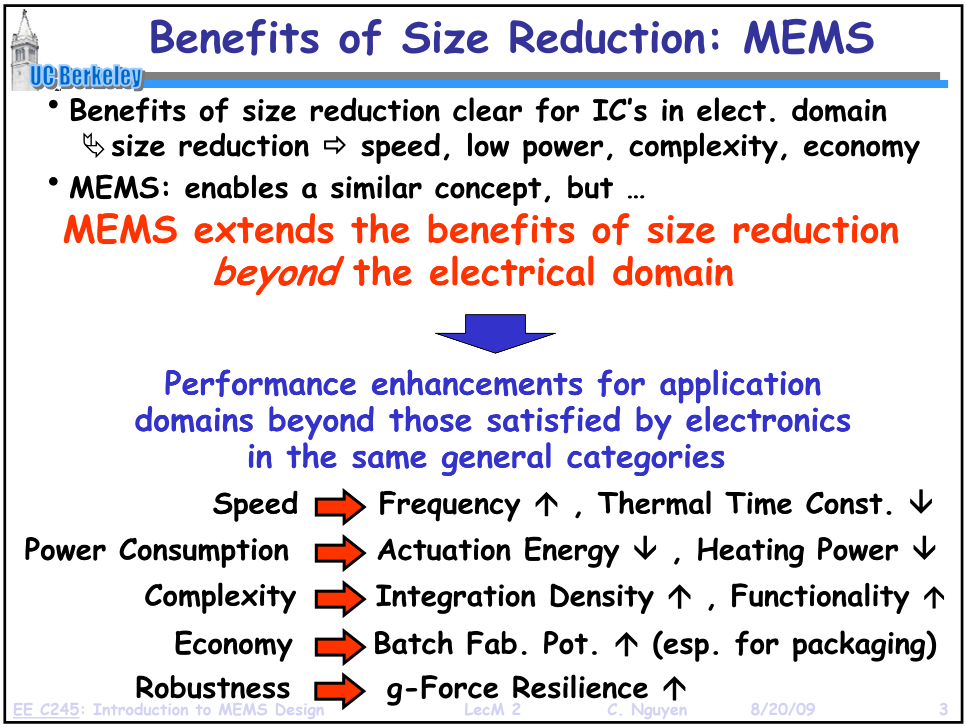
University of California at Berkeley
Berkeley, CA 94720

Lecture Module 2: Benefits of Scaling



Lecture Outline

- Reading: Senturia, Chapter 1
- Lecture Topics:
  - Benefits of Miniaturization
  - Examples
    - GHz micromechanical resonators
    - Chip-scale atomic clock
    - Micro gas chromatograph



Benefits of Size Reduction: MEMS

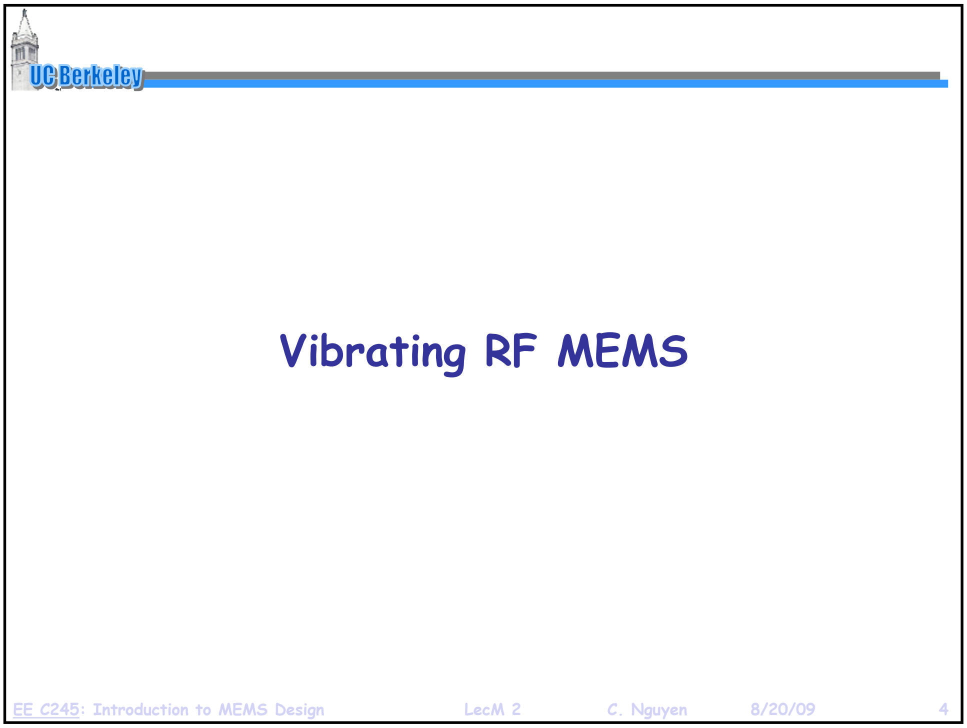
- Benefits of size reduction clear for IC's in elect. domain
  - ↳ size reduction ⇨ speed, low power, complexity, economy
- MEMS: enables a similar concept, but …

MEMS extends the benefits of size reduction *beyond* the electrical domain

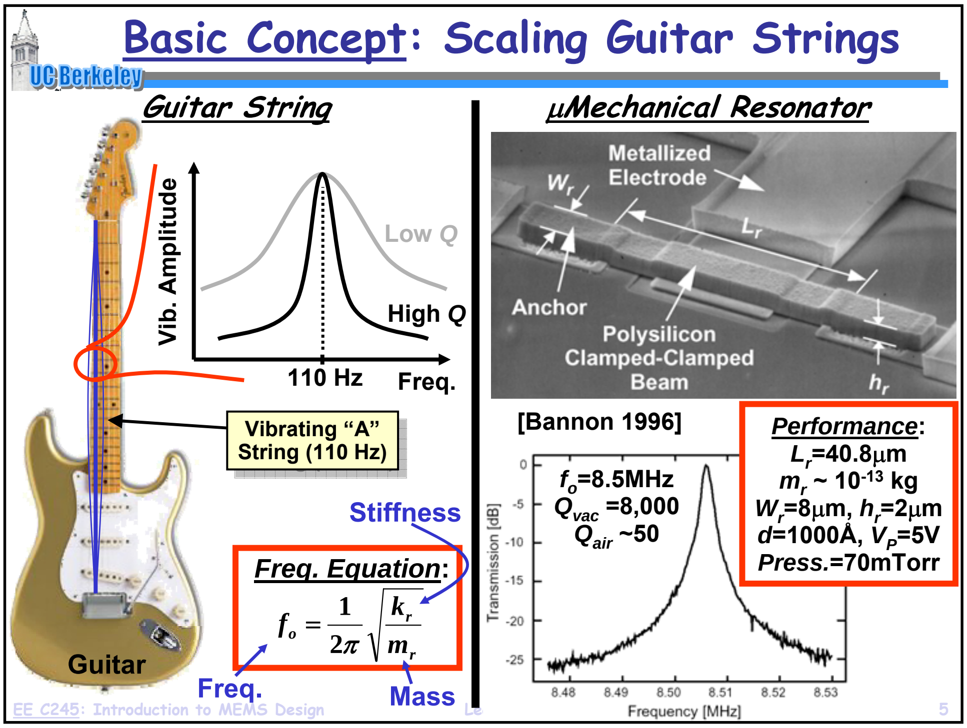
⬇

Performance enhancements for application domains beyond those satisfied by electronics in the same general categories

Speed ➡ Frequency ↑ , Thermal Time Const. ↓
Power Consumption ➡ Actuation Energy ↓ , Heating Power ↓
Complexity ➡ Integration Density ↑ , Functionality ↑
Economy ➡ Batch Fab. Pot. ↑ (esp. for packaging)
Robustness ➡ g-Force Resilience ↑



Vibrating RF MEMS



Basic Concept: Scaling Guitar Strings

Guitar String

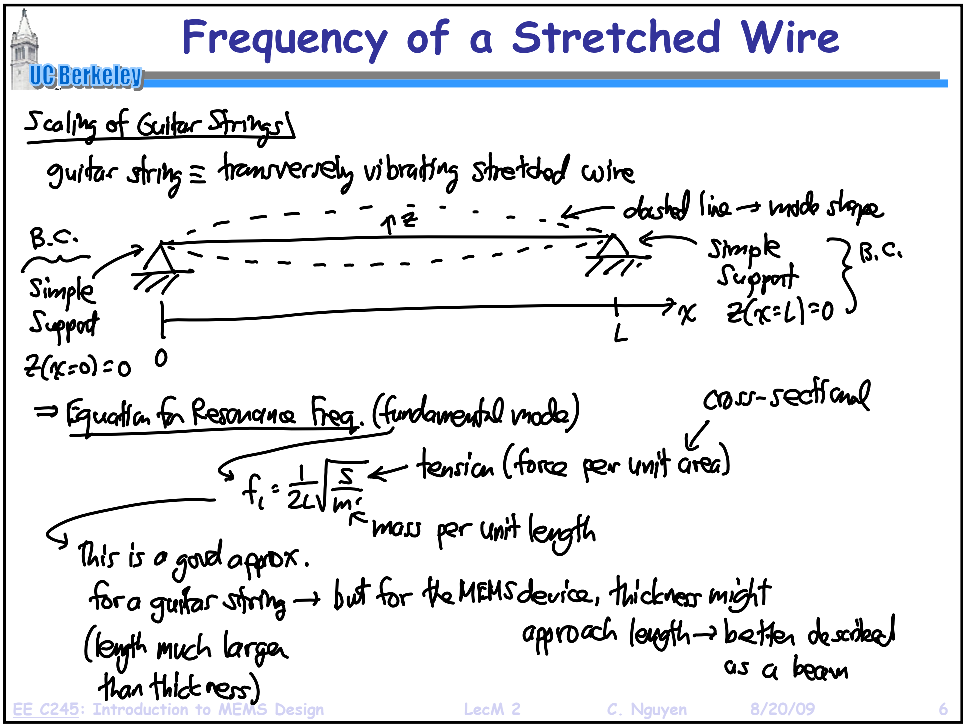
Freq. Equation:

$$f_o = \frac{1}{2\pi}\sqrt{\frac{k_r}{m_r}}$$

μMechanical Resonator

[Bannon 1996]

Performance:
L_r=40.8μm
m_r ~ 10^{-13} kg
W_r=8μm, h_r=2μm
d=1000Å, V_P=5V
Press.=70mTorr



Frequency of a Stretched Wire

Scaling of Guitar Strings

guitar string ≡ transversely vibrating stretched wire

⇒ Equation for Resonance Freq. (fundamental mode)

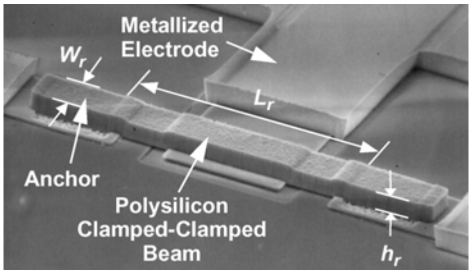
$$f_1 = \frac{1}{2L}\sqrt{\frac{S}{m'}}$$

← tension (force per unit area)
cross-sectional
← mass per unit length

This is a good approx. for a guitar string (length much larger than thickness) → but for the MEMS device, thickness might approach length → better described as a beam

Frequency of a Clamped-Clamped Beam

Clamped-Clamped Beam



⇒ Eq. for Resonance freq.:

$$f_0 = \frac{1}{2\pi}\sqrt{\frac{k}{m}} = 1.03\sqrt{\frac{E}{\rho}}\,\frac{h}{L^2} \qquad (1)$$

where E ≜ Young's modulus [GPa]
ρ ≜ density [kg/m³]
h ≜ thickness [m]
L ≜ length [m]

Example. $L = 40\mu m$, $h = 2\mu m$

polySi → $E = 150\text{ GPa}$, $\rho = 2300\text{ kg/m}^3$

$$\therefore\ f_0 = (1.03)\underbrace{\sqrt{\frac{150G}{2300}}}_{\text{acoustic velocity} = 8{,}076\text{ m/s}}\ \frac{2\mu}{(40\mu)^2} \rightarrow \boxed{f_0 = 10.4\text{MHz}}$$

↘ As L↓ → f_0↑ !

Frequency of a Clamped-Clamped Beam

Example. $L = 4\mu m \rightarrow f_0 = (1.03)(8076)\frac{2\mu}{(4\mu)^2} \rightarrow \boxed{f_0 = 1.04\text{GHz}\,!}$

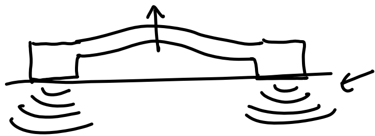
↳ GHz freqs. possible!

Smaller
↓
Faster!

Remarks.

① Eq. (1) not accurate when L≈h. (See HW#1)

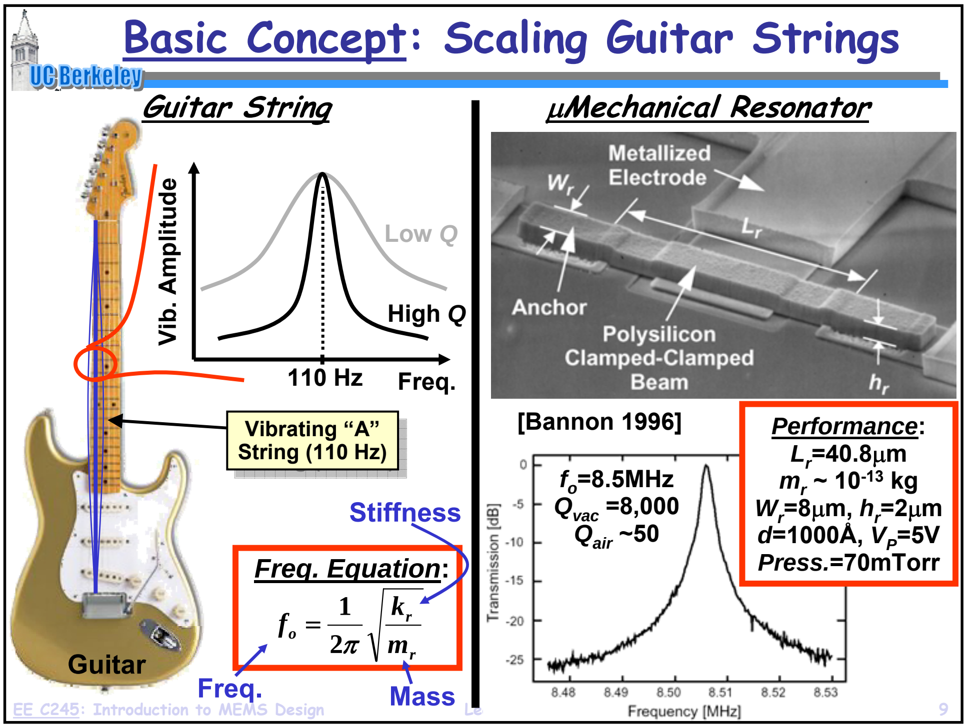
② When L≈h (a when it isn't more than 10×h), anchor losses become an issue



Anchor Radiation → lowers quality factor, Q

③ Solution: nanodimensions? ✓

④ Better Solution: other geometries ✓✓



Basic Concept: Scaling Guitar Strings

Vibrating "A" String (110 Hz)

Freq. Equation:

$$f_o = \frac{1}{2\pi}\sqrt{\frac{k_r}{m_r}}$$

Stiffness

Freq.

Mass

[Bannon 1996]

f_o=8.5MHz
Q_{vac} =8,000
Q_{air} ~50

Performance:
L_r=40.8μm
m_r ~ 10^{-13} kg
W_r=8μm, h_r=2μm
d=1000Å, V_P=5V
Press.=70mTorr

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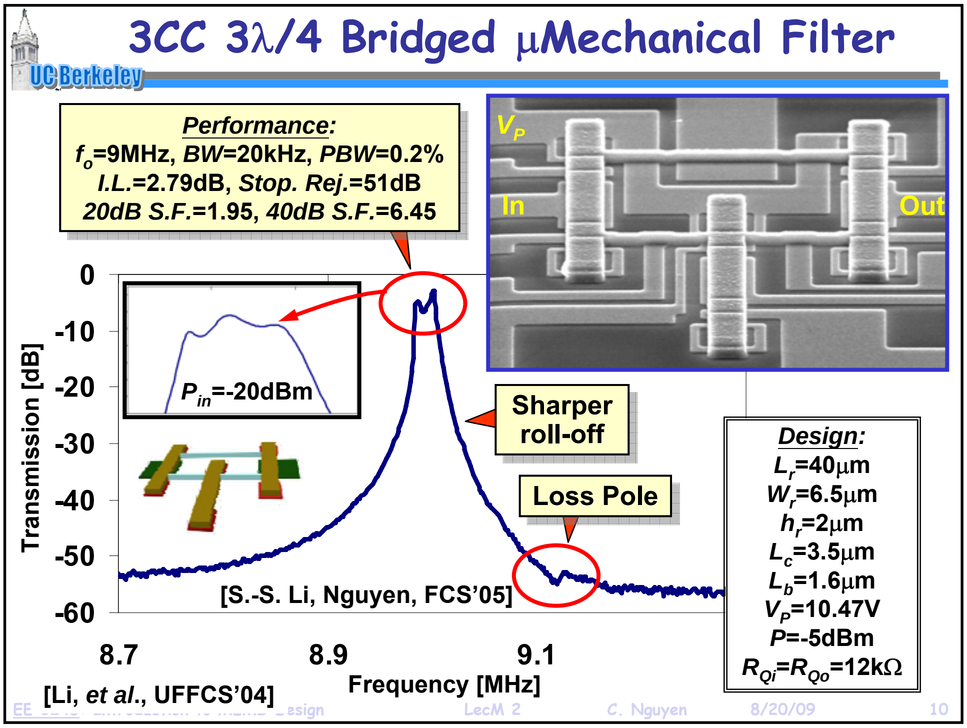

3CC 3λ/4 Bridged μMechanical Filter

Performance:
f_o=9MHz, *BW*=20kHz, *PBW*=0.2%
I.L.=2.79dB, *Stop. Rej.*=51dB
20dB S.F.=1.95, *40dB S.F.*=6.45

[S.-S. Li, Nguyen, FCS'05]

Design:
L_r=40μm
W_r=6.5μm
h_r=2μm
L_c=3.5μm
L_b=1.6μm
V_P=10.47V
P=-5dBm
R_{Qi}=R_{Qo}=12kΩ

[Li, *et al.*, UFFCS'04]

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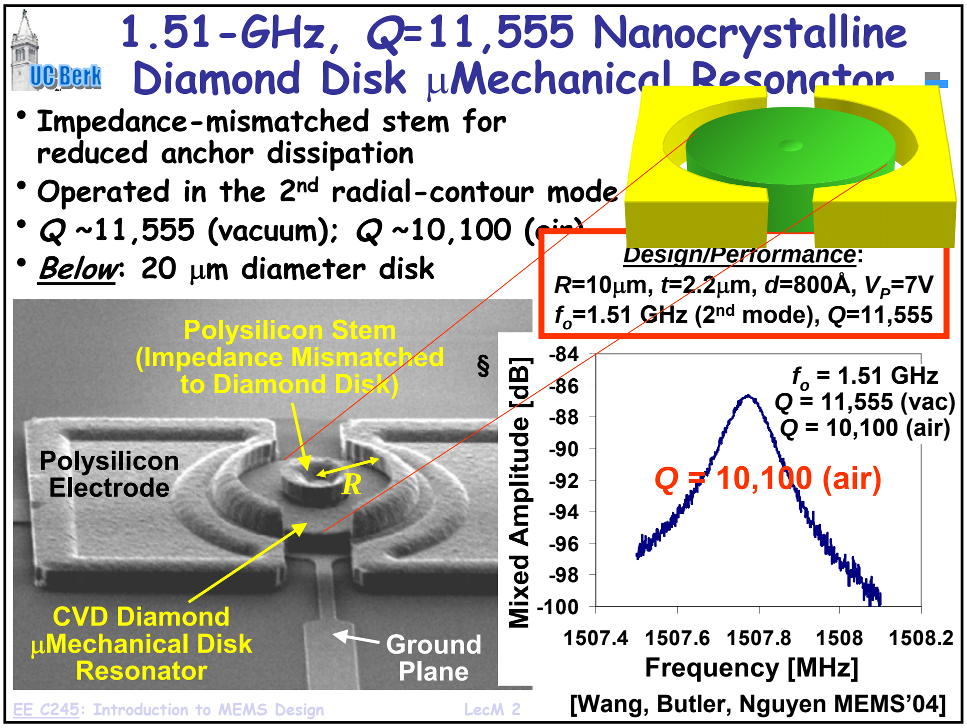
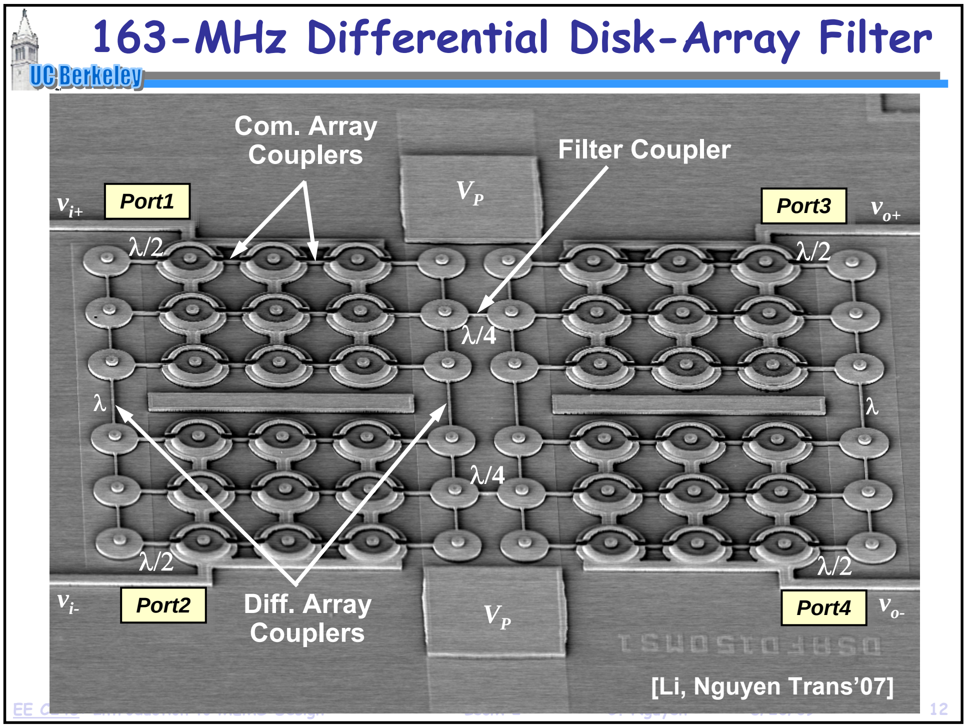


1.51-GHz, Q=11,555 Nanocrystalline Diamond Disk μMechanical Resonator

- Impedance-mismatched stem for reduced anchor dissipation
- Operated in the 2nd radial-contour mode
- Q ~11,555 (vacuum); Q ~10,100 (air)
- ***Below***: 20 μm diameter disk

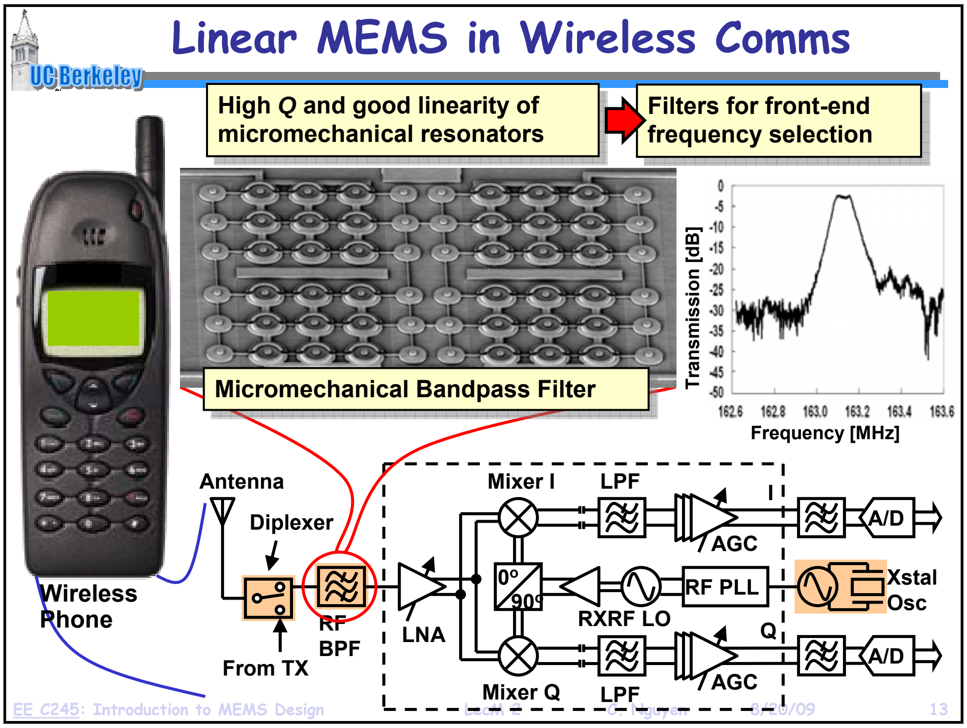
Design/Performance:
R=10μm, t=2.2μm, d=800Å, V_P=7V
f_o=1.51 GHz (2nd mode), Q=11,555

[Wang, Butler, Nguyen MEMS'04]



163-MHz Differential Disk-Array Filter

[Li, Nguyen Trans'07]



Linear MEMS in Wireless Comms

High *Q* and good linearity of micromechanical resonators → **Filters for front-end frequency selection**

Micromechanical Bandpass Filter

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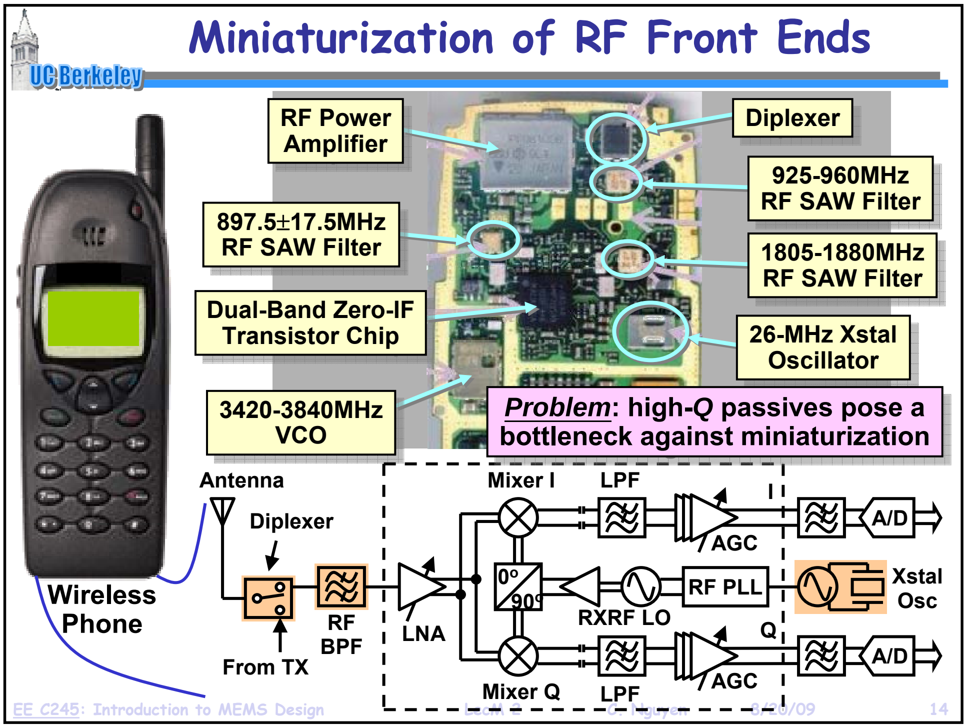

Miniaturization of RF Front Ends

RF Power Amplifier

Diplexer

925-960MHz RF SAW Filter

897.5±17.5MHz RF SAW Filter

1805-1880MHz RF SAW Filter

Dual-Band Zero-IF Transistor Chip

26-MHz Xstal Oscillator

3420-3840MHz VCO

***Problem*: high-*Q* passives pose a bottleneck against miniaturization**

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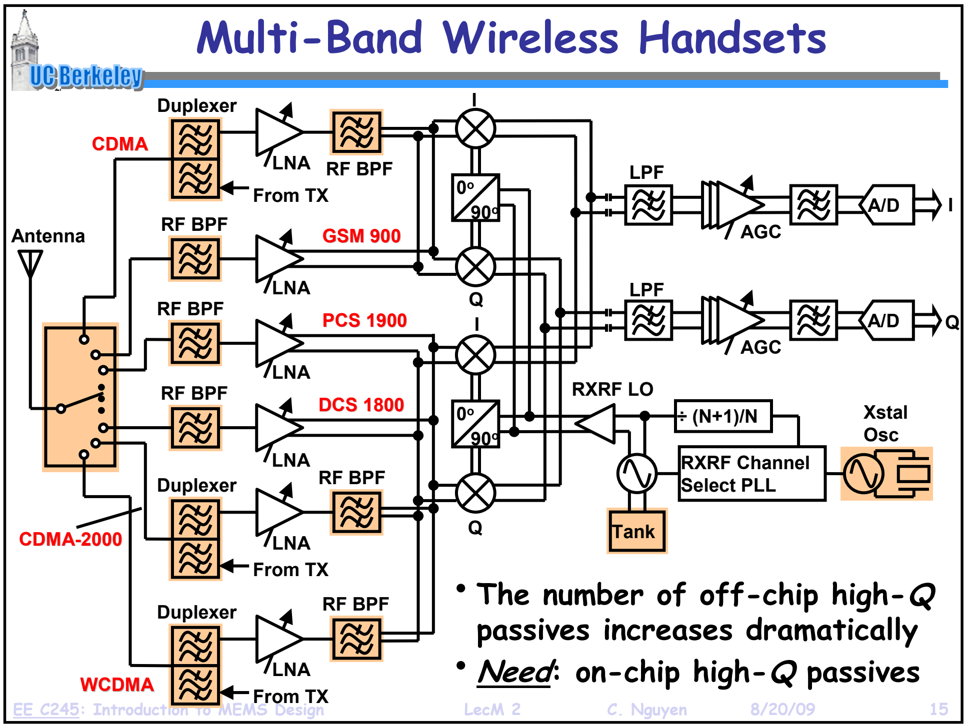

Multi-Band Wireless Handsets

- The number of off-chip high-*Q* passives increases dramatically
- *Need*: on-chip high-*Q* passives

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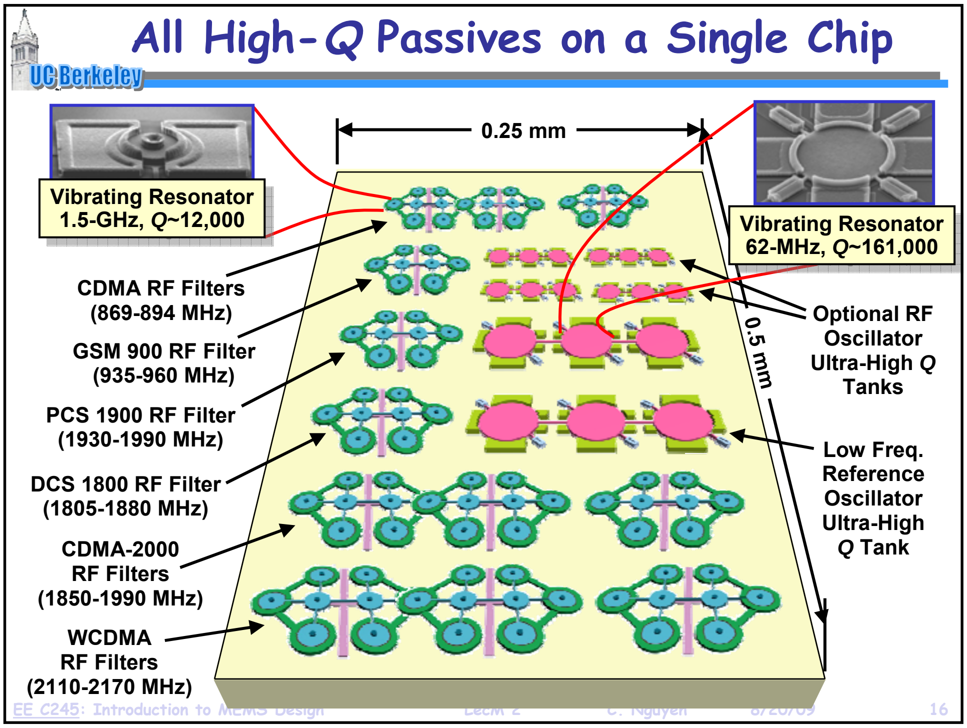

All High-*Q* Passives on a Single Chip

Vibrating Resonator
1.5-GHz, *Q*~12,000

Vibrating Resonator
62-MHz, *Q*~161,000

CDMA RF Filters
(869-894 MHz)

GSM 900 RF Filter
(935-960 MHz)

PCS 1900 RF Filter
(1930-1990 MHz)

DCS 1800 RF Filter
(1805-1880 MHz)

CDMA-2000
RF Filters
(1850-1990 MHz)

WCDMA
RF Filters
(2110-2170 MHz)

Optional RF
Oscillator
Ultra-High *Q*
Tanks

Low Freq.
Reference
Oscillator
Ultra-High
Q Tank

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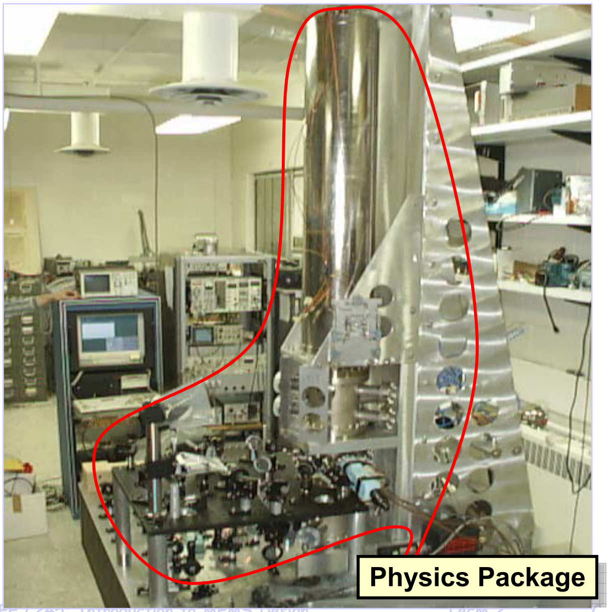
Chip-Scale Atomic Clocks (CSAC)

NIST F1 Fountain Atomic Clock

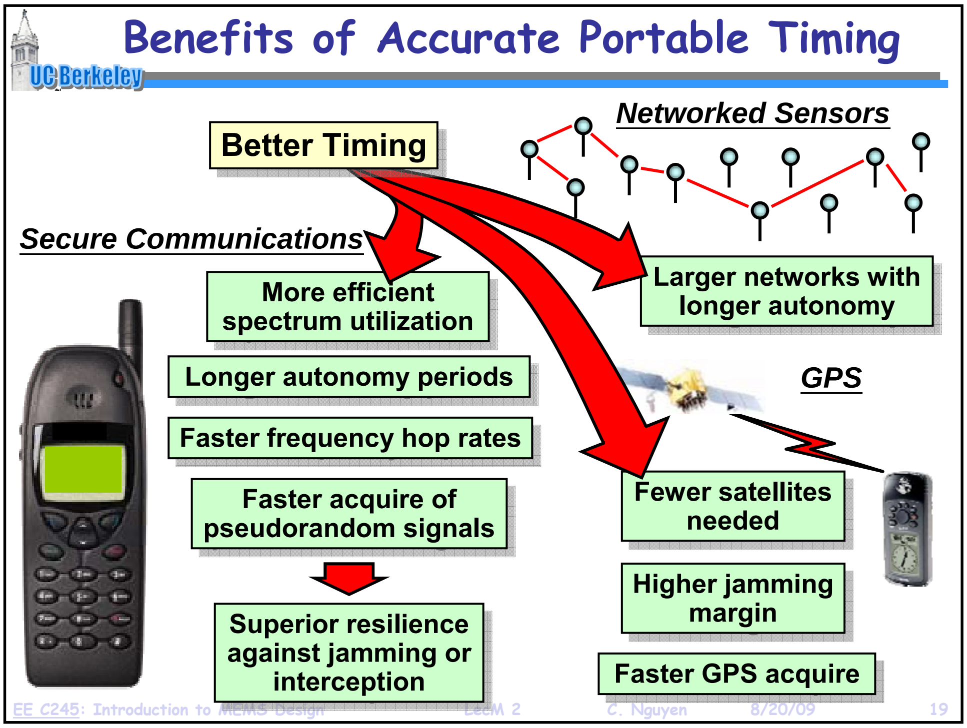


Physics Package

Vol: ~3.7 m^3
Power: ~500 W
Acc: 1×10^{-15}
Stab: 3.3x10^{-15}/hr

After 1 sec ⇨
***Error*: 10^{-15} sec**

Loses 1 sec every 30 million years!



Benefits of Accurate Portable Timing

Better Timing

Secure Communications

- More efficient spectrum utilization
- Longer autonomy periods
- Faster frequency hop rates
- Faster acquire of pseudorandom signals

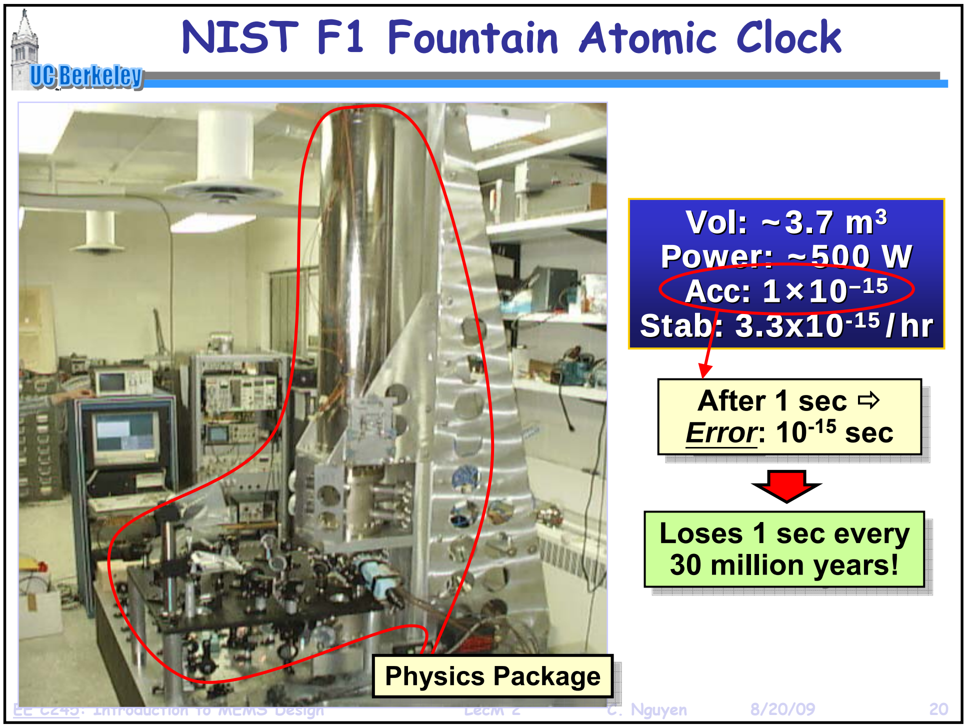
Superior resilience against jamming or interception

Networked Sensors

- Larger networks with longer autonomy

GPS

- Fewer satellites needed
- Higher jamming margin
- Faster GPS acquire

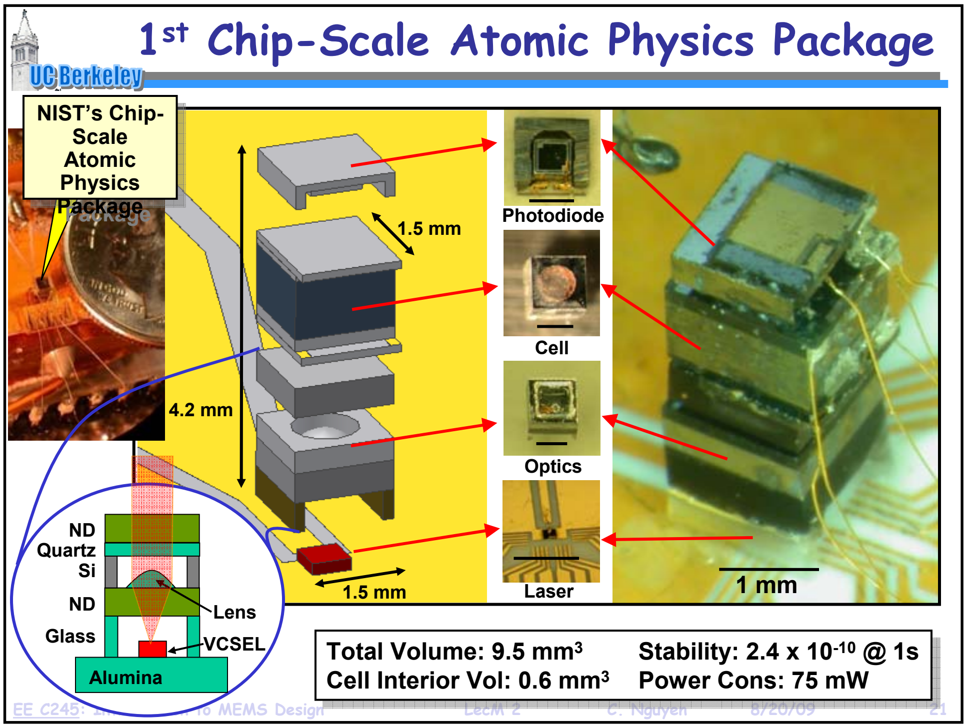


NIST F1 Fountain Atomic Clock

Vol: ~3.7 m^3
Power: ~500 W
Acc: 1×10^{-15}
Stab: $3.3\text{x}10^{-15}$/hr

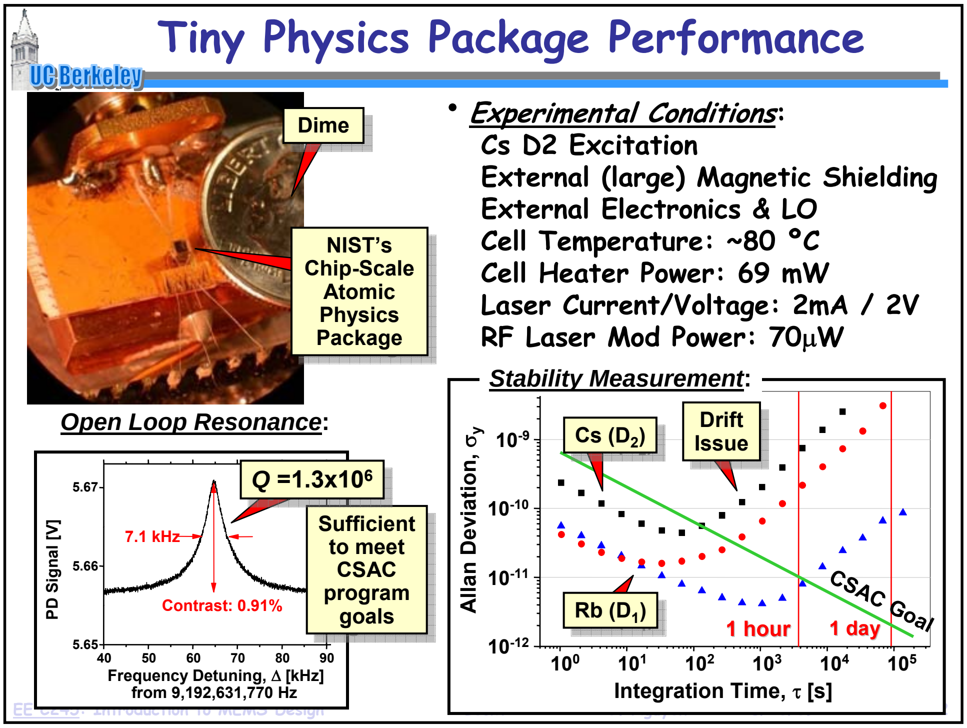
After 1 sec ⇨
Error: 10^{-15} sec

Loses 1 sec every 30 million years!



1st Chip-Scale Atomic Physics Package

Total Volume: 9.5 mm^3
Cell Interior Vol: 0.6 mm^3
Stability: 2.4 x 10^{-10} @ 1s
Power Cons: 75 mW



Tiny Physics Package Performance

- ***Experimental Conditions***:
  - Cs D2 Excitation
  - External (large) Magnetic Shielding
  - External Electronics & LO
  - Cell Temperature: ~80 °C
  - Cell Heater Power: 69 mW
  - Laser Current/Voltage: 2mA / 2V
  - RF Laser Mod Power: 70µW

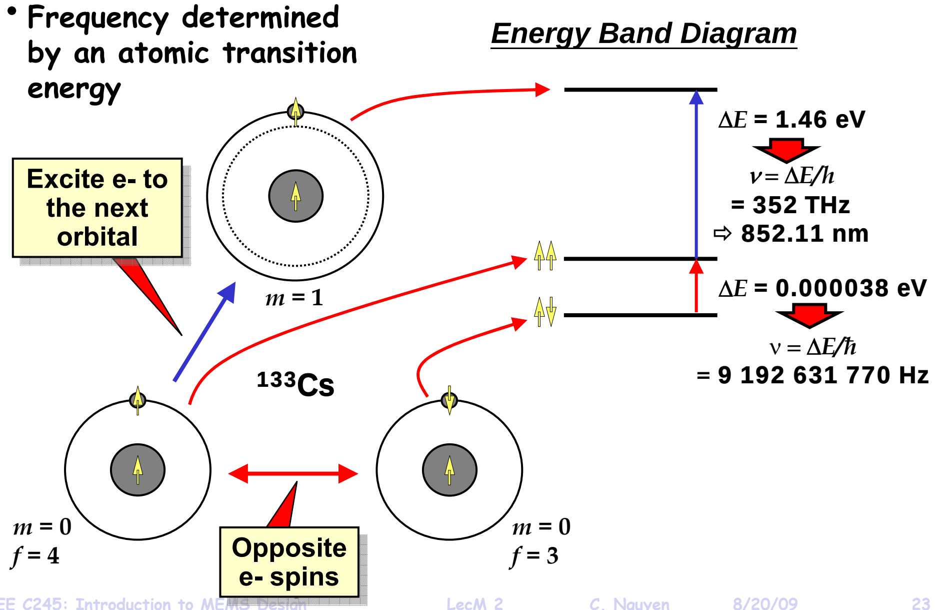
Open Loop Resonance:

Sufficient to meet CSAC program goals

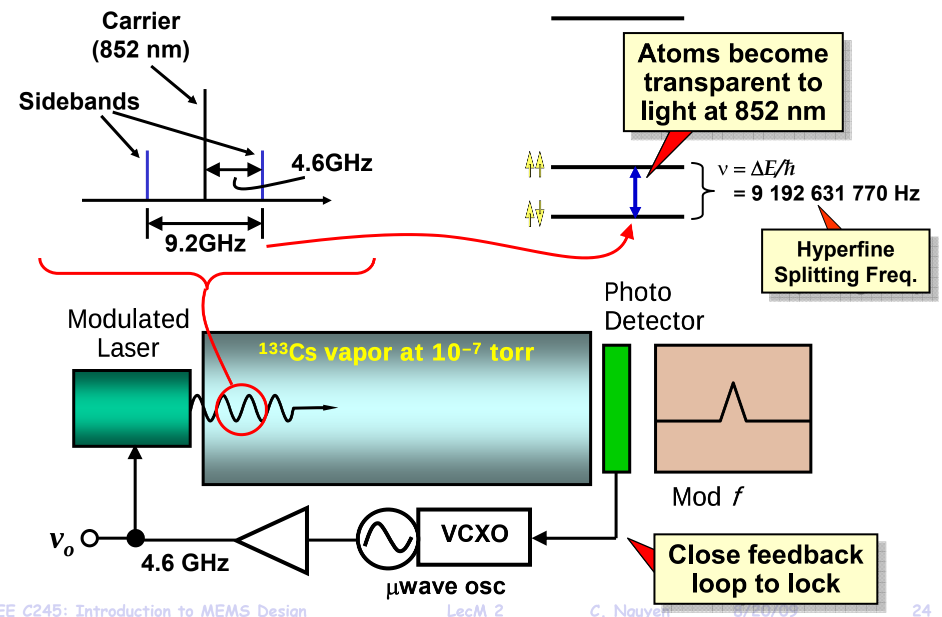
Stability Measurement:

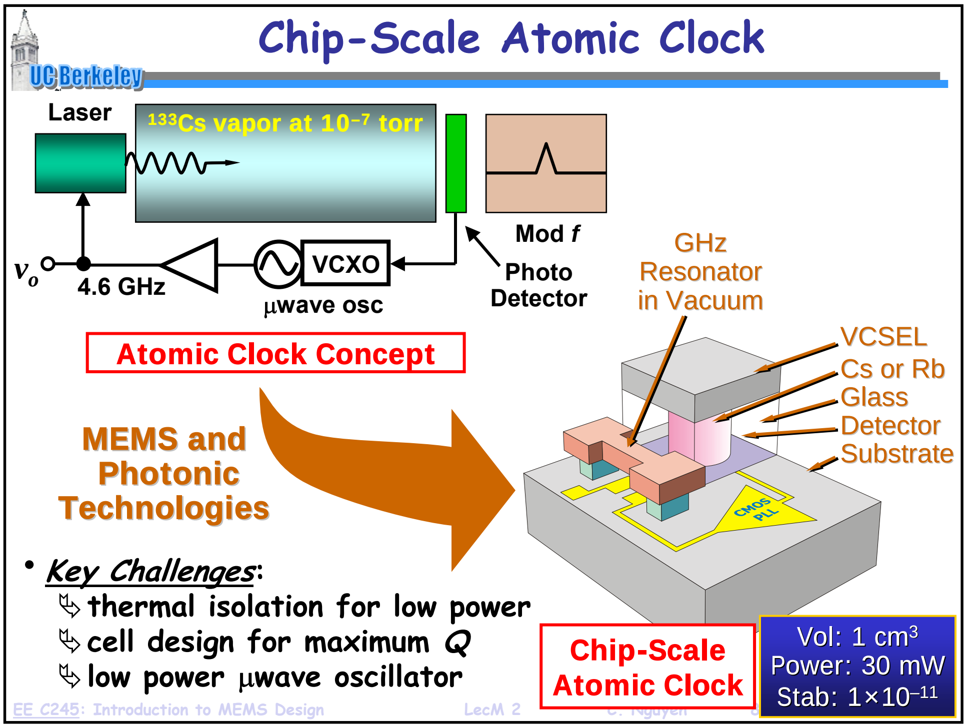
Atomic Clock Fundamentals

- Frequency determined by an atomic transition energy



Miniature Atomic Clock Design



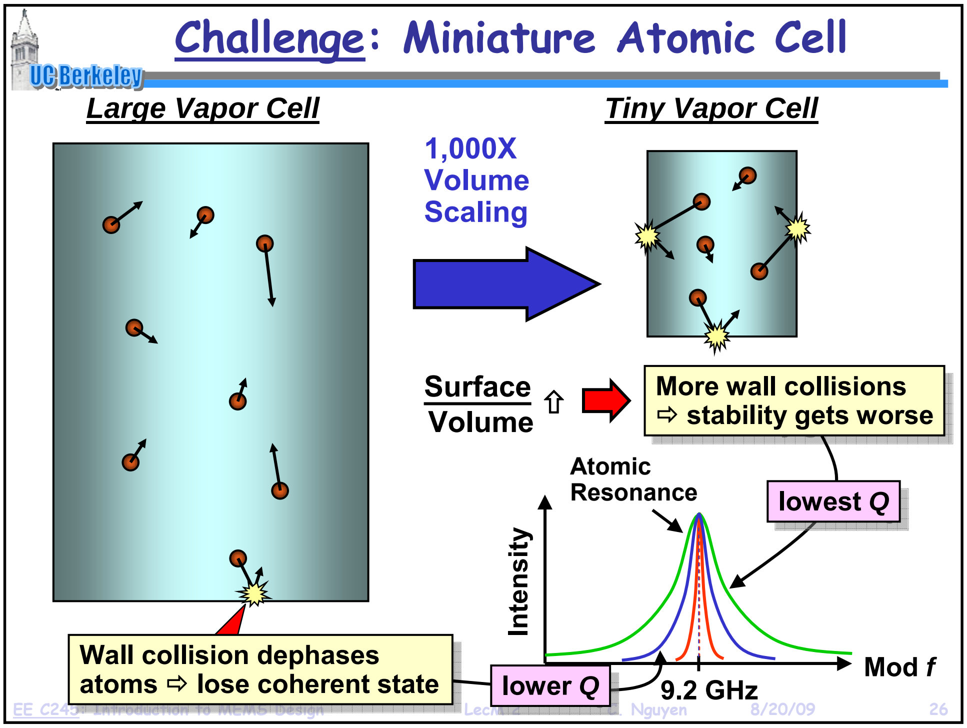


Chip-Scale Atomic Clock

- ***Key Challenges***:
  - ↳ thermal isolation for low power
  - ↳ cell design for maximum *Q*
  - ↳ low power μwave oscillator

Chip-Scale Atomic Clock

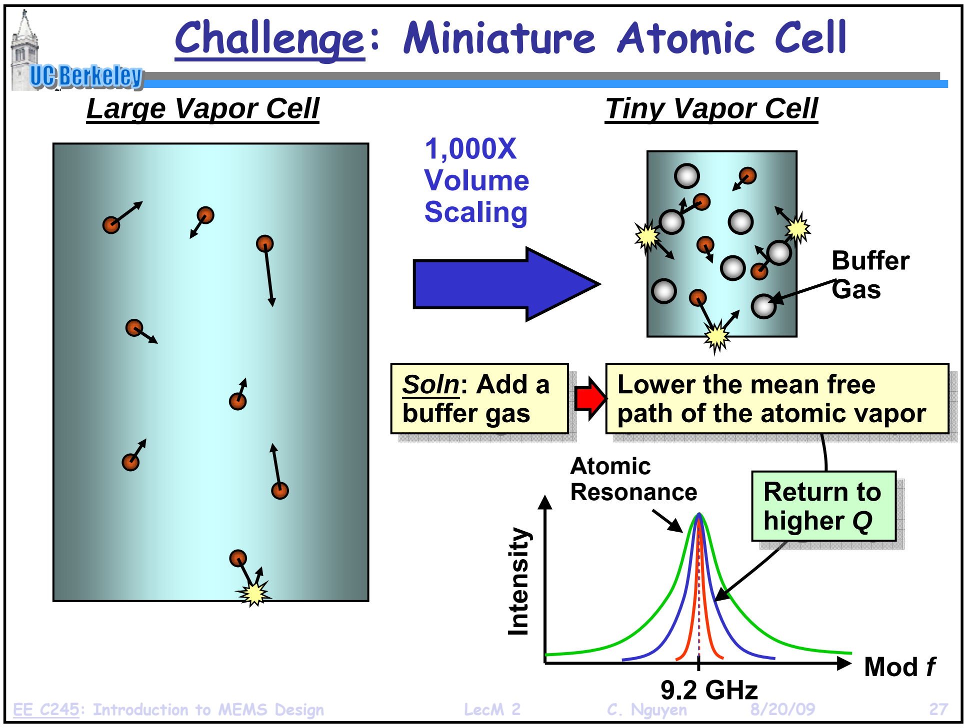
Vol: 1 cm^3
Power: 30 mW
Stab: 1×10^{-11}



Challenge: Miniature Atomic Cell

$\frac{\text{Surface}}{\text{Volume}}$ ⇧ ➡ More wall collisions ⇨ stability gets worse

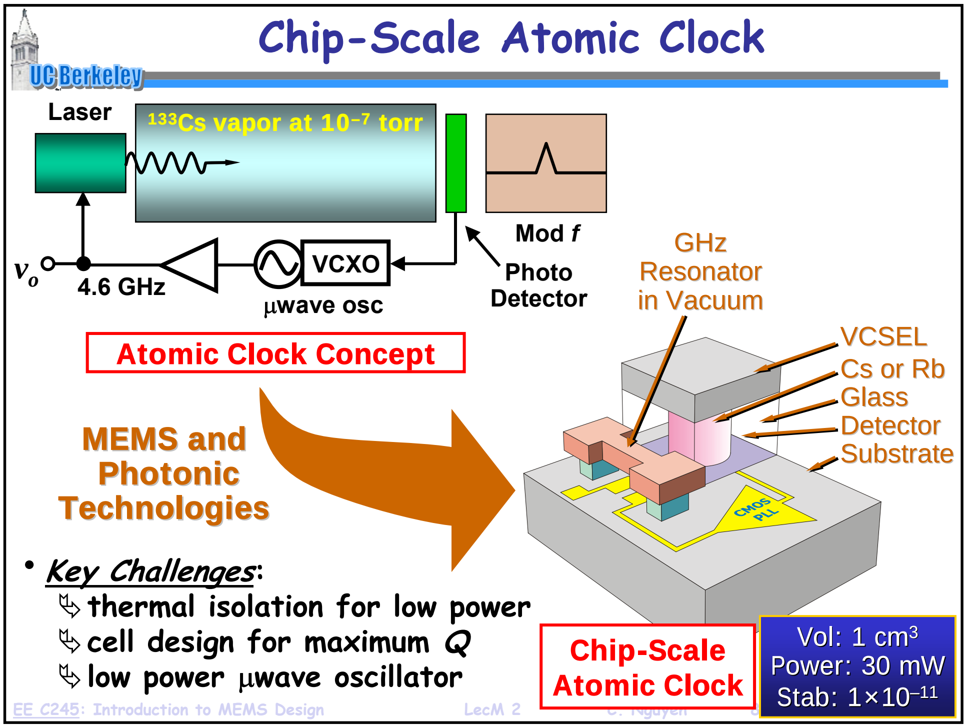
Wall collision dephases atoms ⇨ lose coherent state



Challenge: Miniature Atomic Cell

Soln: Add a buffer gas → Lower the mean free path of the atomic vapor

Return to higher Q



Chip-Scale Atomic Clock

Atomic Clock Concept

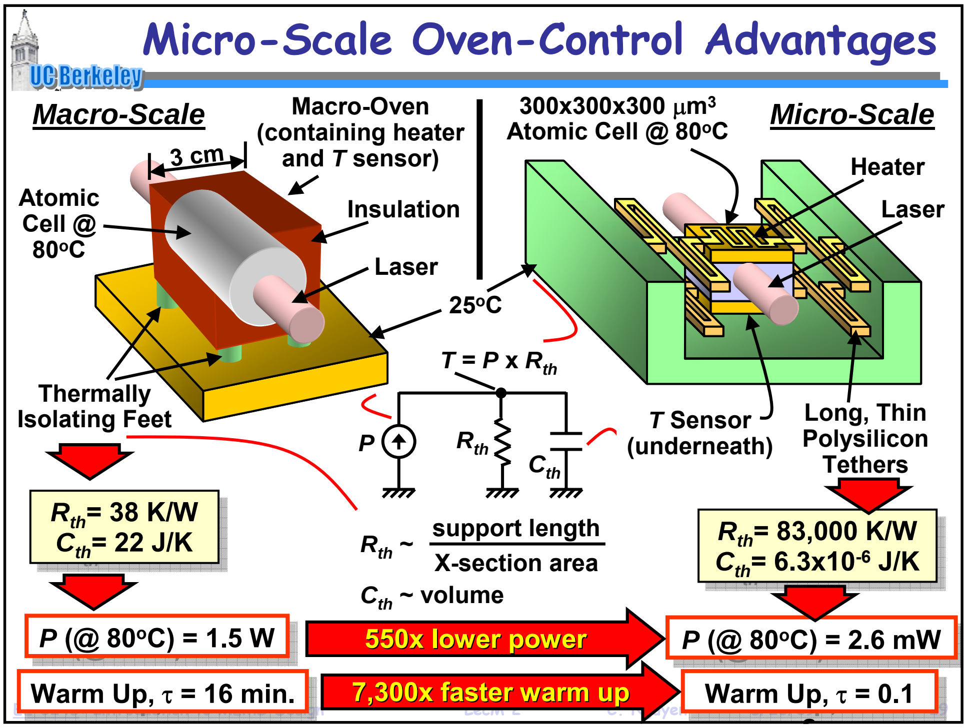
MEMS and Photonic Technologies

- *Key Challenges*:
  - thermal isolation for low power
  - cell design for maximum Q
  - low power μwave oscillator

Chip-Scale Atomic Clock

Vol: 1 cm^3
Power: 30 mW
Stab: 1×10^{-11}

Micro-Scale Oven-Control Advantages



R_{th}= 38 K/W
C_{th}= 22 J/K

R_{th}= 83,000 K/W
C_{th}= 6.3x10^{-6} J/K

$$R_{th} \sim \frac{\text{support length}}{\text{X-section area}}$$

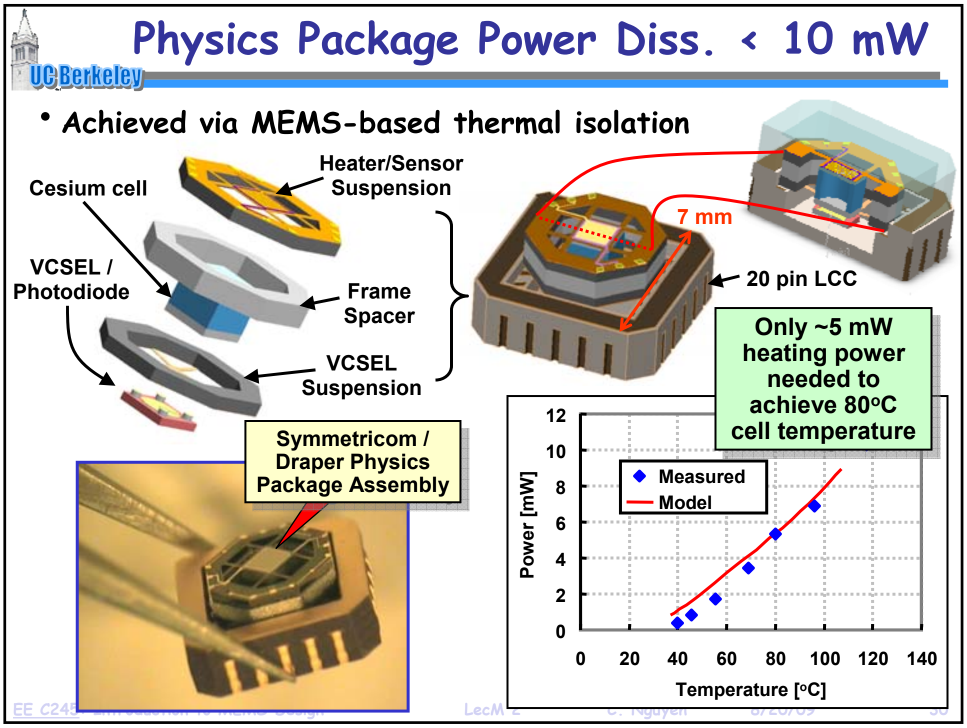
C_{th} ~ volume

P (@ 80°C) = 1.5 W → 550x lower power → P (@ 80°C) = 2.6 mW

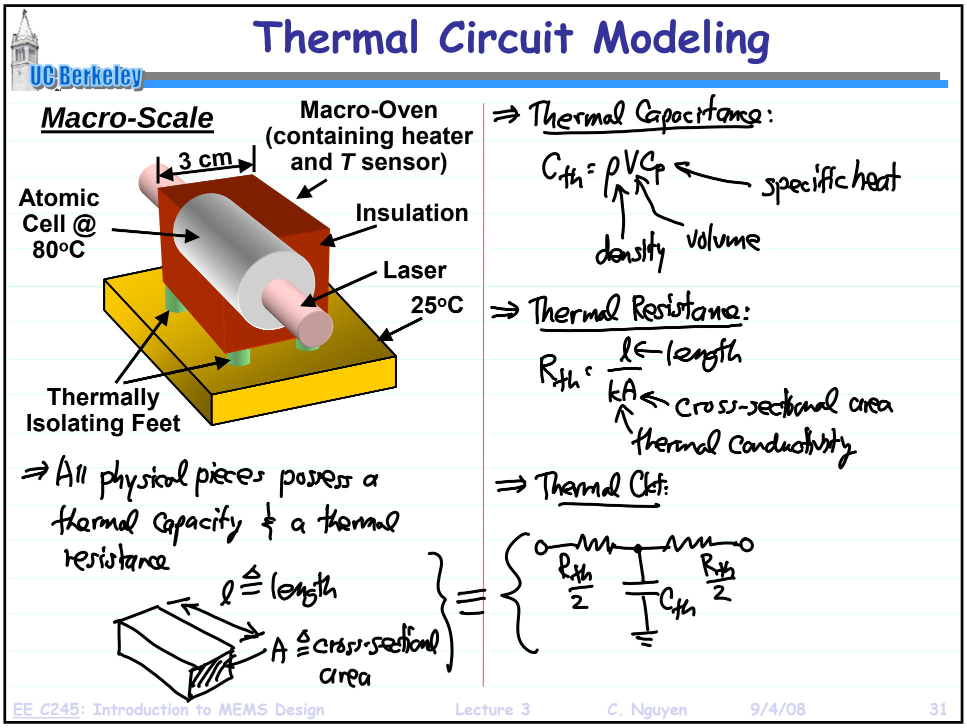
Warm Up, τ = 16 min. → 7,300x faster warm up → Warm Up, τ = 0.1

Physics Package Power Diss. < 10 mW

- Achieved via MEMS-based thermal isolation



Only ~5 mW heating power needed to achieve 80°C cell temperature



Thermal Circuit Modeling

⇒ All physical pieces possess a thermal capacity & a thermal resistance

$l \triangleq$ length

$A \triangleq$ cross-sectional area

⇒ Thermal Capacitance:

$C_{th} = \rho V C_p$ ← specific heat

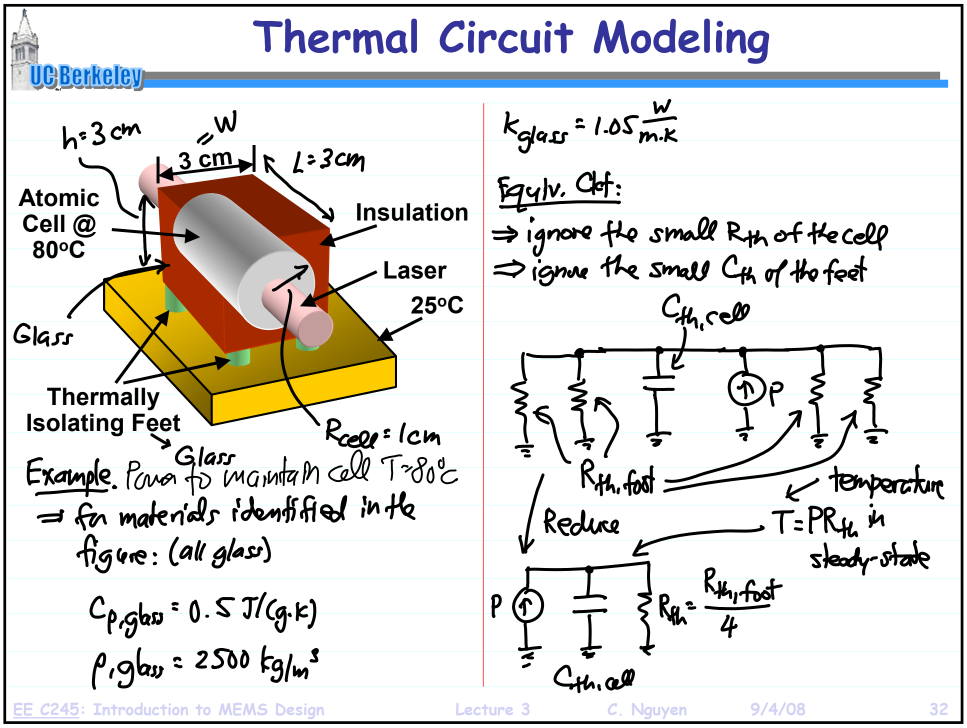
density, volume

⇒ Thermal Resistance:

$R_{th} = \frac{l}{kA}$ l ← length, A ← cross-sectional area, k thermal conductivity

⇒ Thermal Ckt:

$\equiv$



Thermal Circuit Modeling

Example. Power to maintain cell T ~ 80°C

⇒ for materials identified in the figure: (all glass)

$$C_{p,glass} = 0.5\ J/(g \cdot K)$$

$$\rho, glass = 2500\ kg/m^3$$

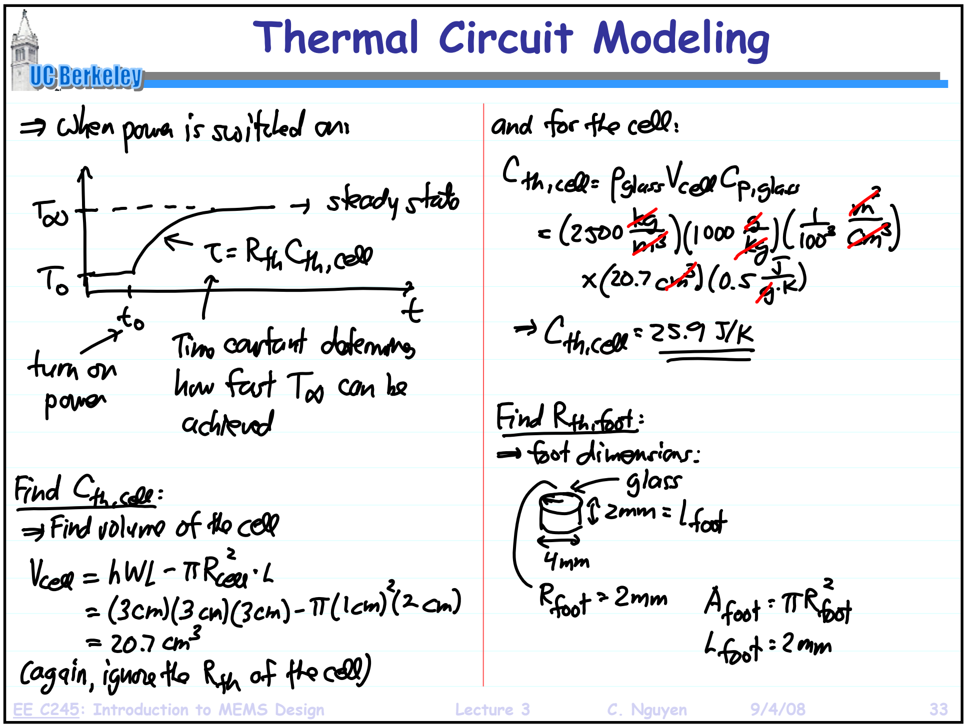
$$k_{glass} = 1.05 \frac{W}{m \cdot K}$$

Equiv. Ckt:

⇒ ignore the small R_{th} of the cell

⇒ ignore the small C_{th} of the feet

temperature ← $T = PR_{th}$ in steady-state



Thermal Circuit Modeling

⇒ When power is switched on:

Time constant determines how fast T_∞ can be achieved

Find $C_{th,cell}$:

⇒ Find volume of the cell

$$V_{cell} = hWL - \pi R_{cell}^2 \cdot L$$
$$= (3cm)(3cm)(3cm) - \pi(1cm)^2(2cm)$$
$$= 20.7\ cm^3$$

(again, ignore the R_{th} of the cell)

and for the cell:

$$C_{th,cell} = \rho_{glass} V_{cell} c_{p,glass}$$
$$= \left(2500 \frac{\cancel{kg}}{\cancel{m^3}}\right)\left(1000 \frac{\cancel{g}}{\cancel{kg}}\right)\left(\frac{1}{100^3} \frac{\cancel{m^3}}{\cancel{cm^3}}\right)$$
$$\times (20.7\ \cancel{cm^3})\left(0.5 \frac{J}{\cancel{g} \cdot K}\right)$$

$$\rightarrow C_{th,cell} = \underline{\underline{25.9\ J/K}}$$

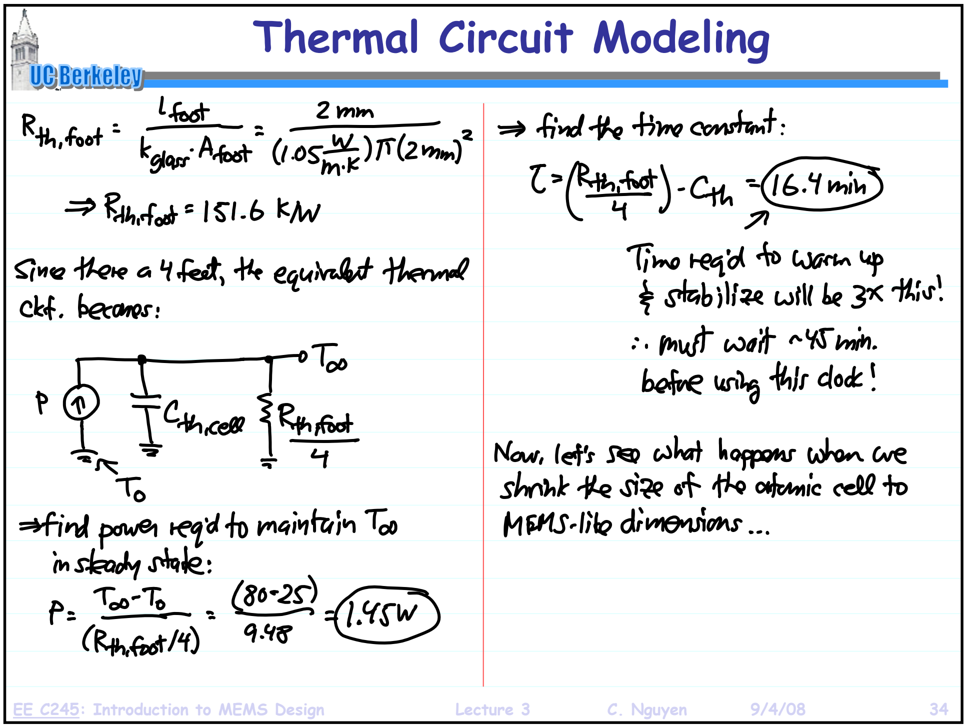
Find $R_{th,foot}$:

→ foot dimensions:

$R_{foot} = 2mm$

$A_{foot} = \pi R_{foot}^2$

$L_{foot} = 2mm$



Thermal Circuit Modeling

$$R_{th,foot} = \frac{L_{foot}}{k_{glass} \cdot A_{foot}} = \frac{2\ mm}{(1.05 \frac{W}{m \cdot K}) \pi (2\ mm)^2}$$

$$\Rightarrow R_{th,foot} = 151.6\ K/W$$

Since there a 4 feet, the equivalent thermal ckt. becomes:

⇒ find power req'd to maintain T_∞ in steady state:

$$P = \frac{T_\infty - T_0}{(R_{th,foot}/4)} = \frac{(80-25)}{9.48} = \boxed{1.45W}$$

⇒ find the time constant:

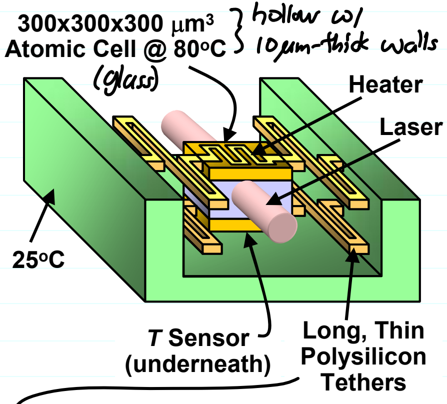
$$\tau = \left(\frac{R_{th,foot}}{4}\right) \cdot C_{th} = \boxed{16.4\ min}$$

Time req'd to warm up & stabilize will be 3x this!

∴ must wait ~45 min. before using this clock!

Now, let's see what happens when we shrink the size of the atomic cell to MEMS-like dimensions...

MEMS Thermal Circuit Modeling



500µm-long, 10µm-thick, 20µm-wide

$V_{cell} = (300\mu)(300\mu)(300\mu) - (280\mu)(280\mu)(280\mu)$

$= 5.048\times10^{-12} m^3$

↳ of course, much smaller than macro

$C_{th,cell} = \rho_{glass} V_{cell} c_{p,glass}$

$= (2500 \frac{kg}{m^3})(5.048\times10^{-12} m^3)$

$\times (500 \frac{J}{kg \cdot K})$

$\Rightarrow C_{th,cell} = \underline{\underline{6.31\times10^{-6}}} \frac{J}{K}$

↳ 4 million x smaller than macro!

$R_{th,supp} = \frac{L_{supp}}{k_{polySi} \cdot W_{supp} \cdot h_{supp}}$

$= \frac{500\mu}{(30 \frac{W}{m \cdot K})(20\mu)(10\mu)} = \underline{\underline{83,333\ K/W}}$

↑ 548x larger

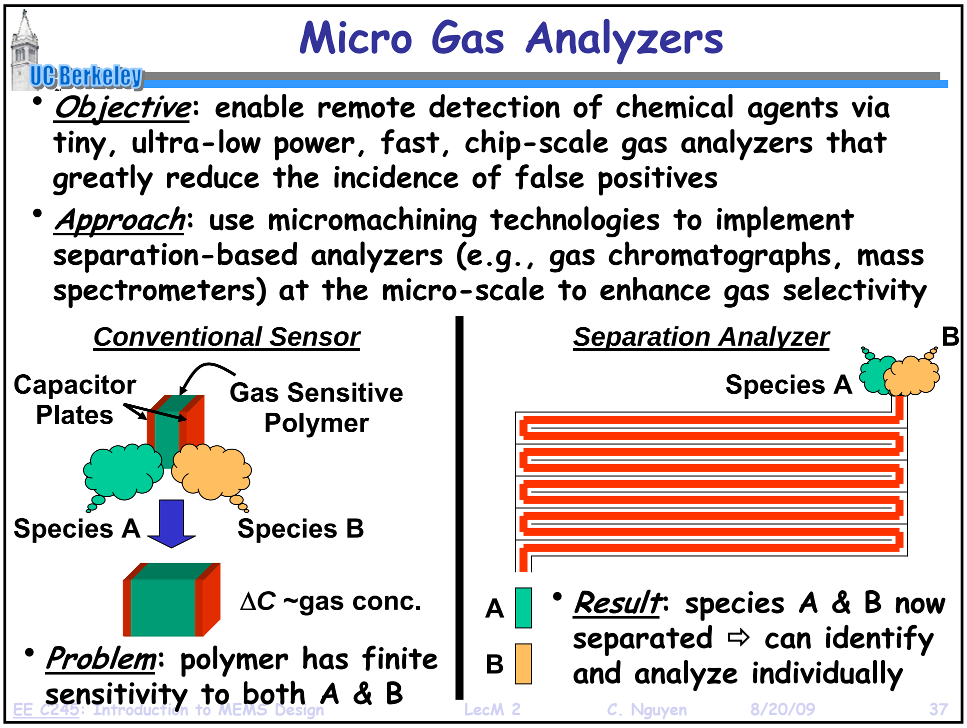
and...

$P = \frac{(80-25)}{83,333} = \boxed{2.64 mW}$ ← 548x smaller!

$\tau = \boxed{0.13 s}$ ← 7300x faster!

All due to scaling!

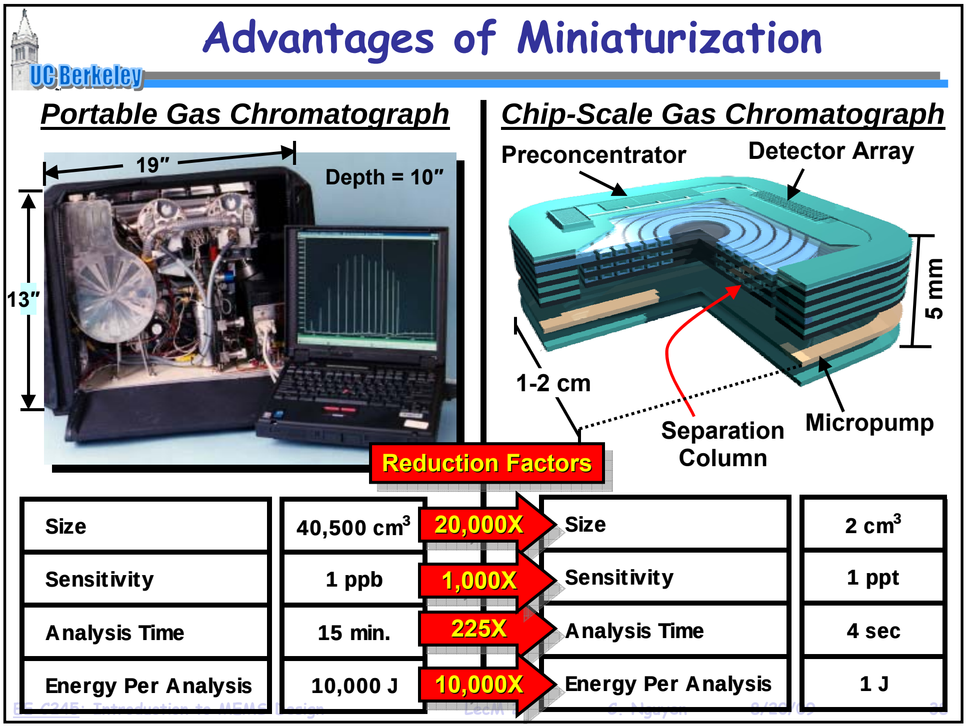
Micro Gas Analyzers (MGA)



Micro Gas Analyzers

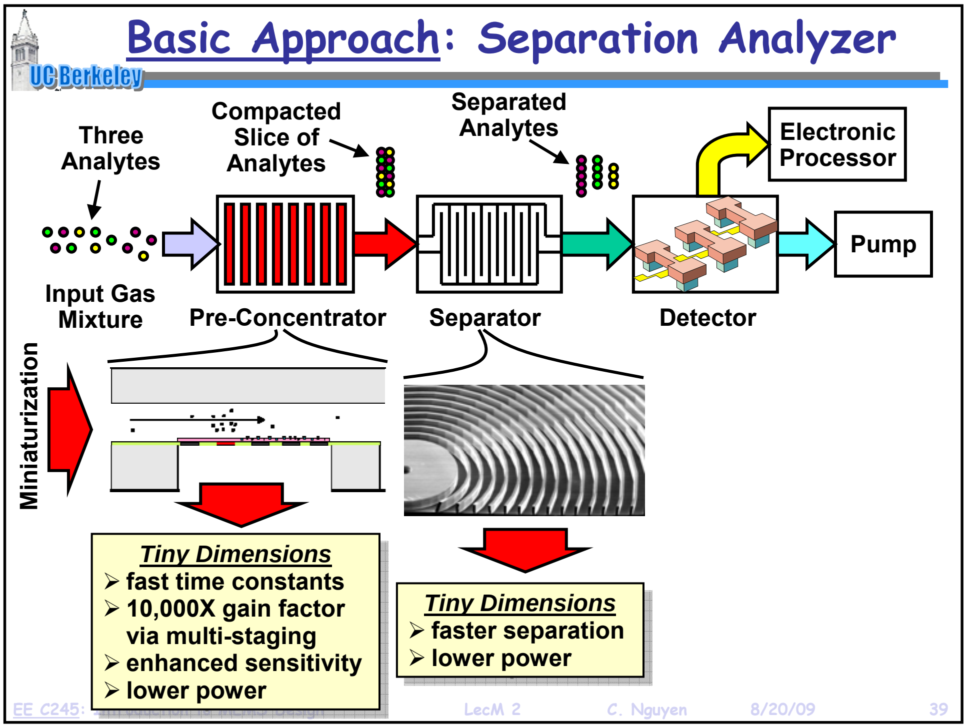
- ***Objective***: enable remote detection of chemical agents via tiny, ultra-low power, fast, chip-scale gas analyzers that greatly reduce the incidence of false positives
- ***Approach***: use micromachining technologies to implement separation-based analyzers (e.g., gas chromatographs, mass spectrometers) at the micro-scale to enhance gas selectivity

- ***Problem***: polymer has finite sensitivity to both A & B
- ***Result***: species A & B now separated ⇨ can identify and analyze individually



Advantages of Miniaturization

Size	40,500 cm^3	20,000X	Size	2 cm^3
Sensitivity	1 ppb	1,000X	Sensitivity	1 ppt
Analysis Time	15 min.	225X	Analysis Time	4 sec
Energy Per Analysis	10,000 J	10,000X	Energy Per Analysis	1 J



Basic Approach: Separation Analyzer

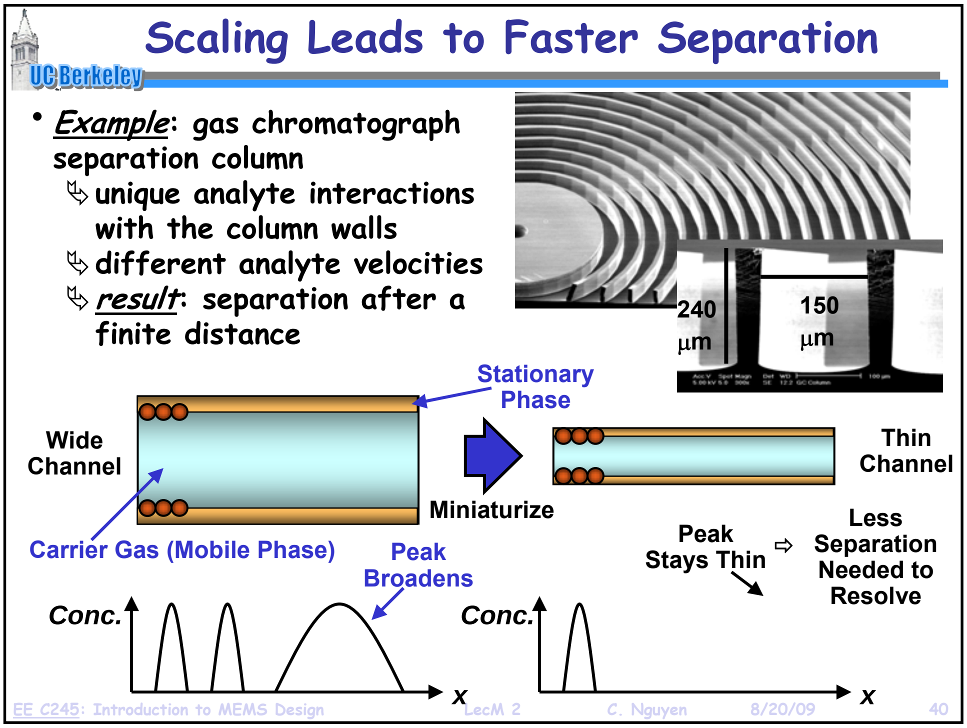
Three Analytes
Compacted Slice of Analytes
Separated Analytes
Electronic Processor
Input Gas Mixture
Pre-Concentrator
Separator
Detector
Pump
Miniaturization

Tiny Dimensions

- fast time constants
- 10,000X gain factor via multi-staging
- enhanced sensitivity
- lower power

Tiny Dimensions

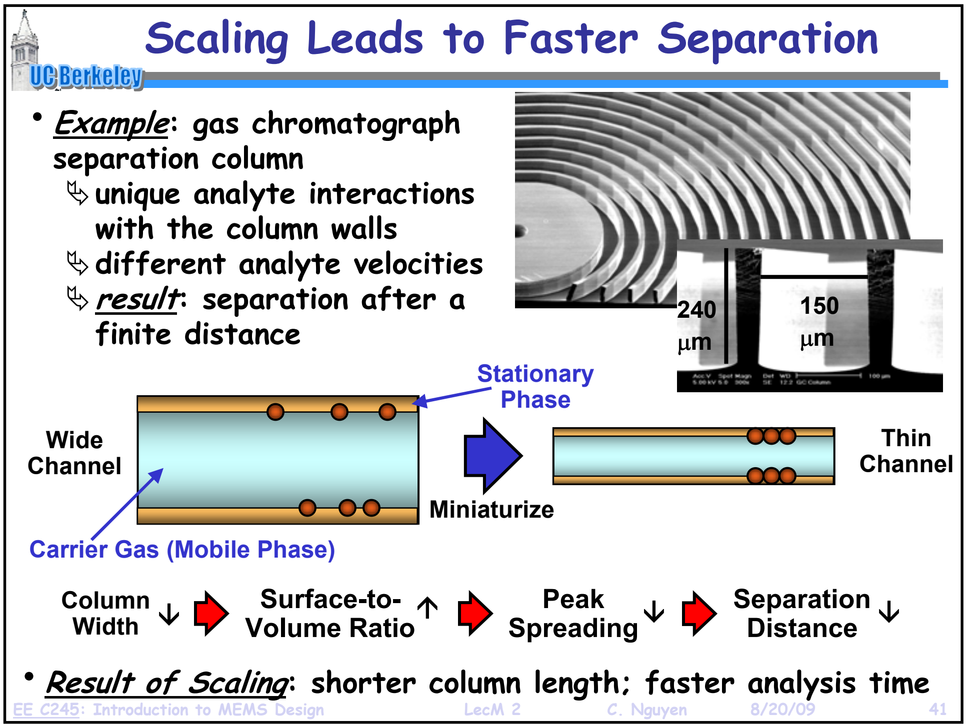
- faster separation
- lower power



Scaling Leads to Faster Separation

- *Example*: gas chromatograph separation column
  - unique analyte interactions with the column walls
  - different analyte velocities
  - *result*: separation after a finite distance

240 µm
150 µm
Stationary Phase
Wide Channel
Miniaturize
Thin Channel
Carrier Gas (Mobile Phase)
Peak Broadens
Peak Stays Thin ⇨ Less Separation Needed to Resolve
Conc.
x
Conc.
x

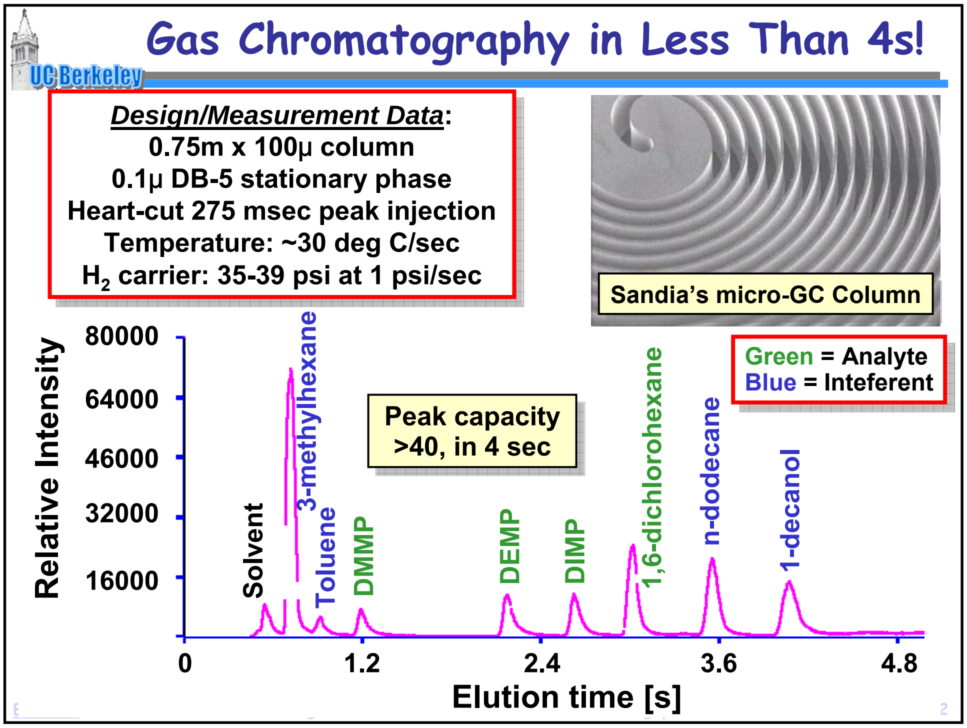


Scaling Leads to Faster Separation

- *Example*: gas chromatograph separation column
  - ↳ unique analyte interactions with the column walls
  - ↳ different analyte velocities
  - ↳ *result*: separation after a finite distance

Column Width ↓ ➡ Surface-to-Volume Ratio ↑ ➡ Peak Spreading ↓ ➡ Separation Distance ↓

- *Result of Scaling*: shorter column length; faster analysis time



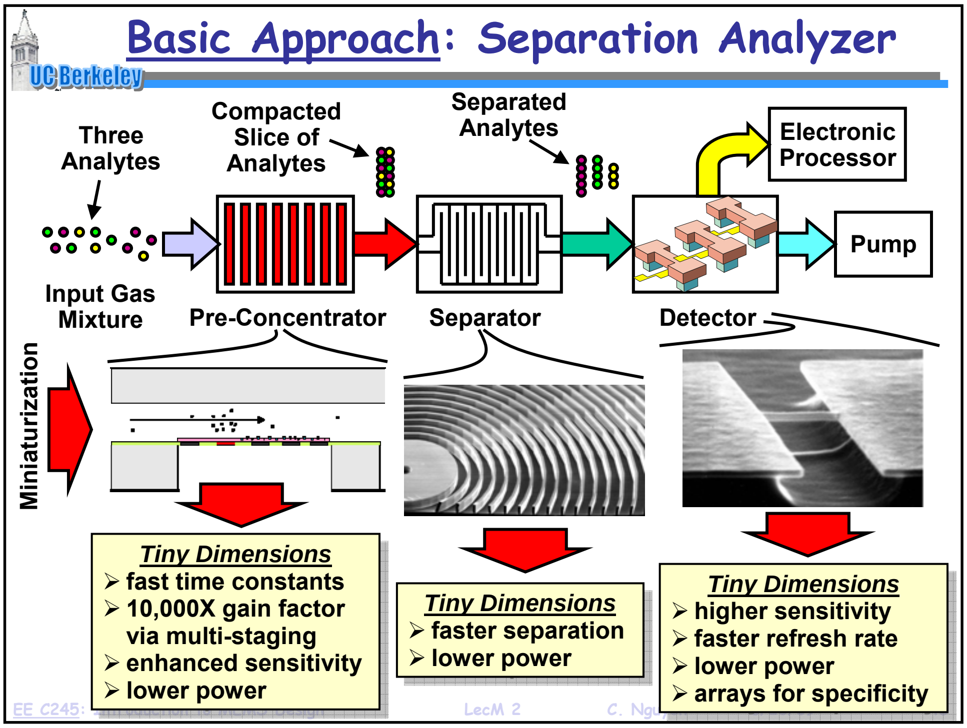
Gas Chromatography in Less Than 4s!

Design/Measurement Data:
0.75m x 100µ column
0.1µ DB-5 stationary phase
Heart-cut 275 msec peak injection
Temperature: ~30 deg C/sec
H_2 carrier: 35-39 psi at 1 psi/sec

Sandia's micro-GC Column

Peak capacity >40, in 4 sec

Green = Analyte
Blue = Inteferent



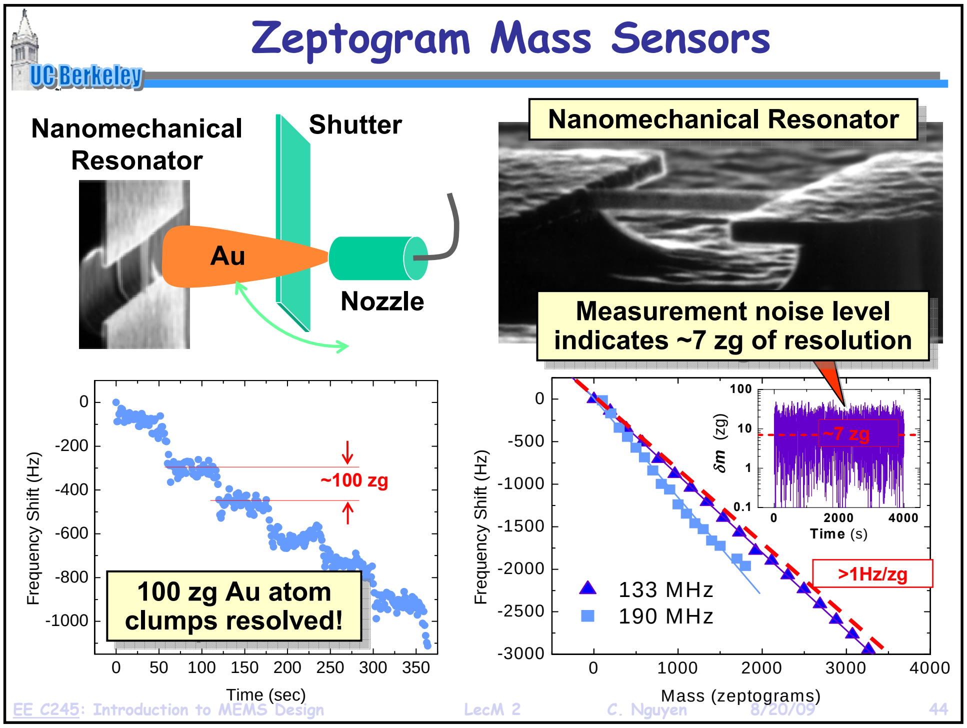
Basic Approach: Separation Analyzer

Tiny Dimensions
- fast time constants
- 10,000X gain factor via multi-staging
- enhanced sensitivity
- lower power

Tiny Dimensions
- faster separation
- lower power

Tiny Dimensions
- higher sensitivity
- faster refresh rate
- lower power
- arrays for specificity

EE C245: LecM 2 C. Ngu

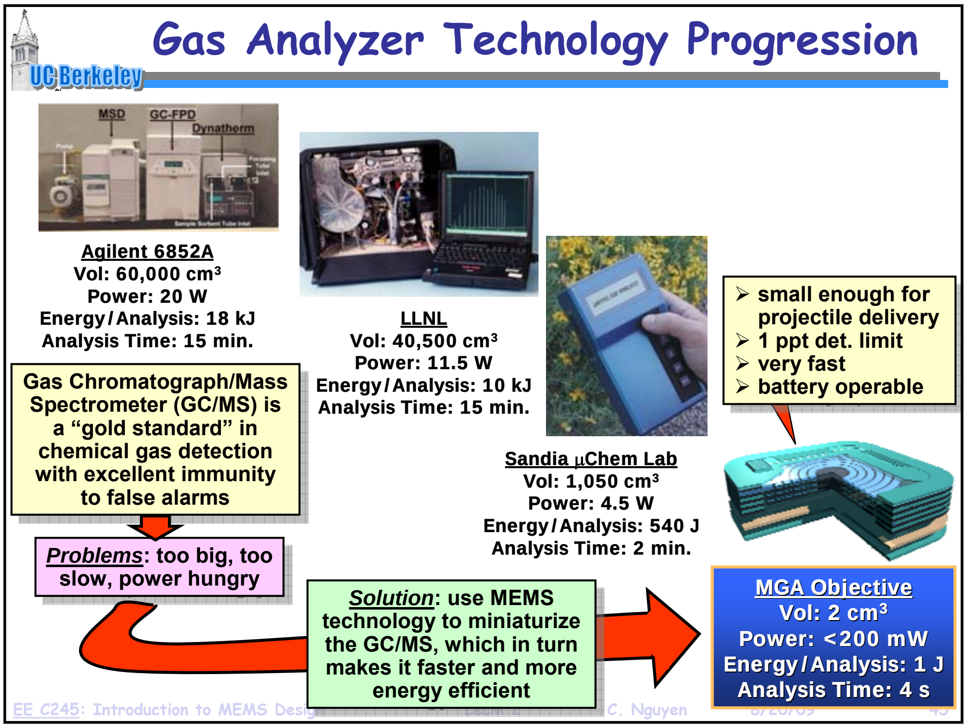


Zeptogram Mass Sensors

100 zg Au atom clumps resolved!

Measurement noise level indicates ~7 zg of resolution

EE C245: Introduction to MEMS Design LecM 2 C. Nguyen 8/20/09 44



Gas Analyzer Technology Progression

Agilent 6852A
Vol: 60,000 cm³
Power: 20 W
Energy/Analysis: 18 kJ
Analysis Time: 15 min.

LLNL
Vol: 40,500 cm³
Power: 11.5 W
Energy/Analysis: 10 kJ
Analysis Time: 15 min.

Sandia µChem Lab
Vol: 1,050 cm³
Power: 4.5 W
Energy/Analysis: 540 J
Analysis Time: 2 min.

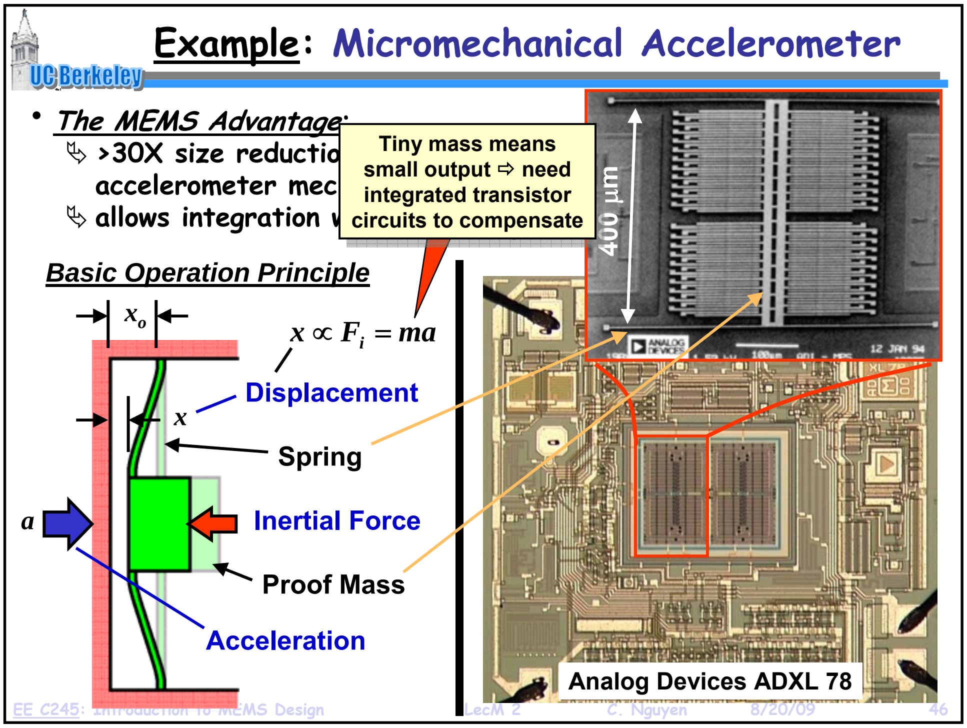
- small enough for projectile delivery
- 1 ppt det. limit
- very fast
- battery operable

Gas Chromatograph/Mass Spectrometer (GC/MS) is a "gold standard" in chemical gas detection with excellent immunity to false alarms

Problems: too big, too slow, power hungry

Solution: use MEMS technology to miniaturize the GC/MS, which in turn makes it faster and more energy efficient

MGA Objective
Vol: 2 cm³
Power: <200 mW
Energy/Analysis: 1 J
Analysis Time: 4 s



Example: Micromechanical Accelerometer

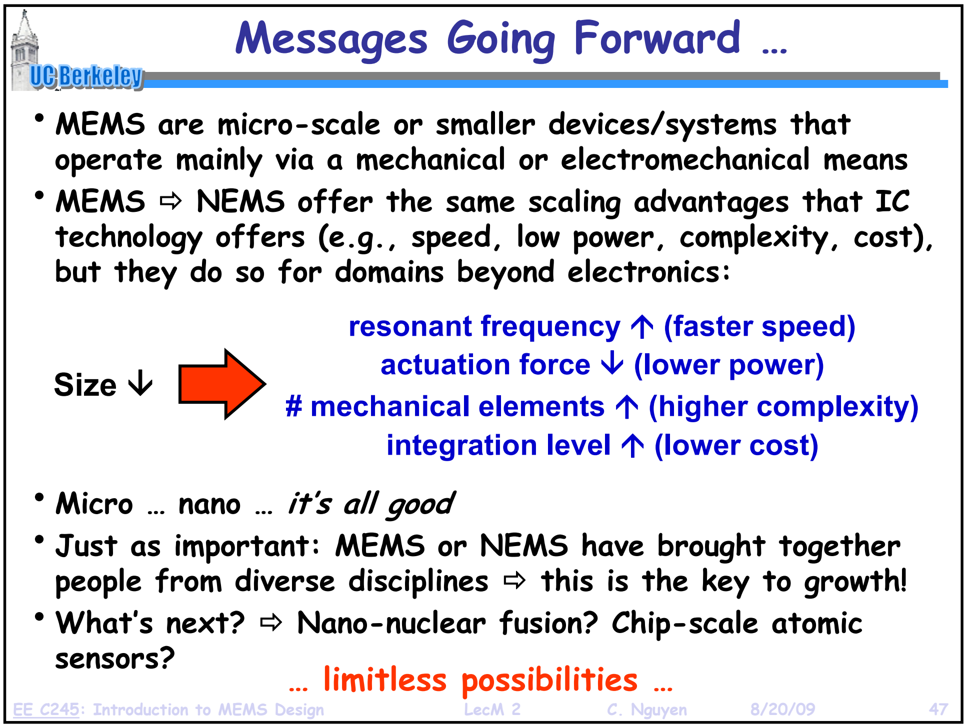
- *The MEMS Advantage:*
  - >30X size reductio accelerometer mec
  - allows integration

Tiny mass means small output ⇨ need integrated transistor circuits to compensate

Basic Operation Principle

$x \propto F_i = ma$

Analog Devices ADXL 78



Messages Going Forward …

- MEMS are micro-scale or smaller devices/systems that operate mainly via a mechanical or electromechanical means
- MEMS ⇨ NEMS offer the same scaling advantages that IC technology offers (e.g., speed, low power, complexity, cost), but they do so for domains beyond electronics:

Size ↓

resonant frequency ↑ (faster speed)
actuation force ↓ (lower power)
mechanical elements ↑ (higher complexity)
integration level ↑ (lower cost)

- Micro … nano … *it's all good*
- Just as important: MEMS or NEMS have brought together people from diverse disciplines ⇨ this is the key to growth!
- What's next? ⇨ Nano-nuclear fusion? Chip-scale atomic sensors?

… limitless possibilities …